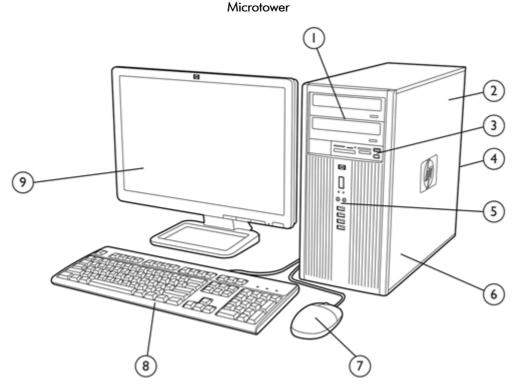
Overview

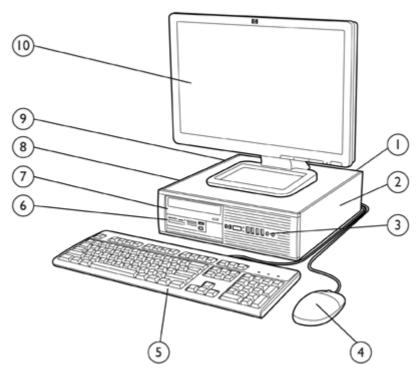


- (2) 5.25" external optical disk drive bays
 (2) 3.5" internal hard disk drive bays
- 320-watt standard efficiency power supply, Active Power Factor Correction (PFC) Optional: 89% efficient energy saving power supply
- 3. (1) 3.5" external bay for optional HP 22-in-1 Media Card Reader, pocket media drive, or other 3.5" device
- Rear I/O: (6) USB 2.0, (1) standard serial port, (1) optional serial port, (1) optional parallel port, (2) PS/2, (1) RJ-45, (1) VGA, (1) audio in, (1) audio out, (1) Display Port
- 5. Front I/O: (4) USB 2.0, headphone and microphone, Dual Color Diagnostic LEDs
- 6. (1) full-height PCI slot, (2) full-height PCIe x1 slots, (1) fullheight PCIe x16 (ADD2/SDVO) slot
- 7. HP Optical Scroll Mouse (PS/2 or USB), or HP USB Laser Mouse
- 8. HP Standard Keyboard (PS/2 or USB) or HP USB Smartcard Keyboard
- 9. HP monitor (sold separately)



Overview

Small Form Factor



- 1. Rear I/O: (6) USB 2.0, (1) standard serial port, (1) optional 6. serial port, (1) optional parallel port, (2) PS/2, (1) RJ-45, (1) VGA, audio in/out , (1) DisplayPort
- 2. (1) low profile PCI slot, (2) low profile PCIe x1 slots, (1) low profile PCle x16 (SDVO/ADD2) slot
- 3. Front I/O: (4) USB 2.0, headphone and microphone, Dual 8. Color Diagnostic LEDs
- HP Optical Scroll Mouse (PS/2 or USB), or HP USB Laser 4. Mouse
- HP Standard Keyboard (PS/2 or USB) or HP USB Smartcard 10. HP Monitor (sold separately) 5. Keyboard

(1) 3.5" external bay for optional HP 22-in-1 Media Card Reader, pocket media drive, or other 3.5" device

- (1) 5.25" external bay for optional optical drive, or other 7. 5.25" device (bay tilts up for device removal and insertion)
 - (1) 3.5-inch internal drive bay supporting primary hard disk drive
- 9. 240-watt power supply Optional: 89% efficient energy saving power supply



Overview

At A Glance

- The HP Compaq 6000 Pro Business PC is designed to be the foundation of your business with enhanced features and proven technology
- Intel® Q43 Express chipset, Intel Core™ 2 Duo processors, Intel Core 2 Quad processors, and Intel Graphics Media Accelerator 4500 integrated graphics
- Embedded TPM1.2 compliant security module* (Vista Bit-Locker ready)
- Support for up to 500-GB SATA 3.0Gb/s Smart IV hard drives
- Value-added software on select models
 - O HP Support Assistant
 - O HP Software Agent
 - O McAfee Anti-Virus with 60 day Live Update Subscription
 - O HP Vision Diagnostics software
 - O Microsoft Office 2007
 - O PDF Complete
 - O Computrace Enabler for Desktops (select countries)
 - O HP System Software manager
 - O HP Power Manager
 - O Firefox- HP Virtual Browser
- Value-added software available for free download from the Web (http://www.hp.com/go/easydeploy)
 - O HP Client Automation Starter Edition
 - o HP SoftPaq Download Manager
 - O HP System Software Manager
 - O HP Client Catalog for Microsoft SMS
- Fully compatible software OS image across all models (Microtower, Small Form Factor)
- HP BIOS for security, manageability and software image stability
- Protected by HP Services, including standard warranties up to 5-5-5 (terms and conditions vary by country; certain restrictions and exclusions apply)
- Selected configurations with global availability easily set up and ordered through HP.com Business to Business portals (http://h10019.www1.hp.com/business-site/index.html)
- Tailored HP Factory Express deployment and lifecycle services available (http://h71028.www7.hp.com/enterprise/cache/97688-0-0-225-121.aspx)

*TPM module disabled where use is restricted by law; for example, Russia.

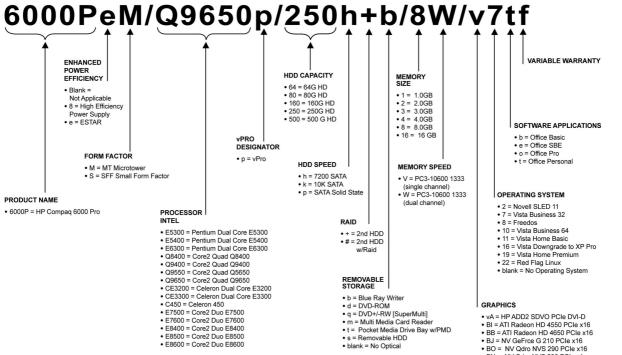
NOTE: This document is a Worldwide document. All features are not available in all regions.

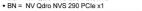


Configurable Components - Select Models (localized by Regions)

Model Key and Example

NOTE: This diagram is an example that illustrates how to read the model number. It is not intended to give every available configuration choice specified in the body of this document and may include references to features that are out of date and no longer available. Because the configurations offered vary by region, some features listed may not be available in all countries.





• AW = NV Qdro NVS 295 256MB DH PCIe x16



Standard Features and Configurable Components (availability may vary by country)

Operating System - One of the following	Preinstalled	Genuine Windows 7 Professional Edition 32* Genuine Windows 7 Professional Edition 64*
One of the following		Windows XP Professional (available through downgrade rights
		from Genuine Windows 7 Professional)*+
		Genuine Windows 7 Home Premium Edition 32*
		Genuine Windows 7 Home Premium Edition 64*
		Genuine Windows 7 Home Basic Edition 32*
		Genuine Windows Vista Business 32**
		Genuine Windows Vista Home Basic 32**
		Windows XP Professional (available through downgrade rights from Genuine Windows Vista Business)**++
		Novell SUSE Linux Enterprise Desktop 11† FreeDOS
	Supported	Genuine Windows Vista Business 64**
		Genuine Windows Vista Enterprise 32**
		Genuine Windows Vista Enterprise 64**
	Certified	Novell SUSE Linux Enterprise Desktop 11†
		Red Hat Enterprise Linux 64++
	NOTE: Windows VP Made	everile bla en e concereta doumland for Windows 7 Professional w

NOIE: Windows XP Mode, available as a separate download for Windows 7 Professional, works with virtualization software such as Windows Virtual PC to run older Windows XP business software on the Windows 7 desktop.

* Offered when Windows 7 is generally available. System may require upgraded and/or separately purchased hardware and/or a DVD drive to install the Windows 7 software and take full advantage of Windows 7 functionality.

See http://www.microsoft.com/windows/windows-7/ for details.

** Certain Windows Vista product features require advanced or additional hardware. See: http://www.microsoft.com/windowsvista/getready/hardwareregs.mspx and: http://www.microsoft.com/windowsvista/getready/capable.mspx for details. Windows Vista Upgrade Advisor can help you determine which features of Windows Vista will run on your computer. To

download the tool, visit: http://www.windowsvista.com/upgradeadvisor.

+ Windows 7 Professional disk may also be included for future upgrade if desired. To qualify for this downgrade an end user must be a business (including governmental or educational institutions) and is expected to order annually at least 25 customer systems with the same custom image.

++ Windows Vista Business disk may also be included for future upgrade if desired. To qualify for this downgrade an end user must be a business (including governmental or educational institutions) and is expected to order annually at least 25 customer systems with the same custom image.

⁺ The following features are not supported by Novell SUSE Linux Enterprise Desktop:

- HP 22-in-1 Media Card Reader with PCI Card
- DisplayPort
- HP ProtectTools
- SATA Blu-ray Writer playback of commercial movies
- Intel Gigabit CT Desktop NIC •
- Broadcom NetXtreme Gigabit Ethernet PCIe NIC Plus Card
- HP ADD2 SDVO PCIe DVI-D adapter



Standard Features and Configurable Components (availability may vary by country)

- 2nd serial port adapter (including low profile)
- Power Management features (US ENERGY STAR)

⁺⁺ The following features are not supported by Red Hat Enterprise Linux 64:

- HP 22-in-1 Media Card Reader with PCI Card
- Integrated 1.2 TPM Embedded Security Chip
- Intel Gigabit CT Desktop NIC
- Broadcom NetXtreme Gigabit Ethernet PCIe NIC Plus Card (DASH functionality)
- LSI PCEe x1 Hi-Speed 56K International SoftModem
- HP ADD2 SDVO PCIe DVI-D adapter
- HP FireWire / IEEE 1394 PCI Card (full height and low profile)
- 2nd serial port adapter (including low profile)
- HP Wireless 802.11b/g/n PCle x1 Card
- HP USB Smartcard Keyboard
- Power Management features (US ENERGY STAR)
- SATA Blu-ray Writer
- Broadcom NetXtreme Gigabit Ethernet Plus (DASH 1.1) PCIe NIC Card
- ATI Radeon HD 4550 Dual Head PCIe x16 Graphics Card
- ATI Radeon HD 4650 (1 GB DH) PCIe x16 Graphics Card
- NVIDIA GeForce 310 DP PCIe x16 Graphics Card
- NVIDIA Quadro NVS 290 (256MB DH) PCIe x16 Graphics Card
- NVIDIA Quadro NVS 290 PCIe x1 Graphics Card
- NVIDIA Quadro NVS 295 (256MB DH) PCIe x16 Graphics Card

Value-added Software (on select models; not included with FreeDOS)	HP Software Agent HP Support Assistant HP Systems Software Manager	Microsoft Office 2007 Basic Microsoft Office 2007 Personal Microsoft Office 2007 Professional Microsoft Office 2007 Small Business Edition DASH 1.1 Manageability*		
	HP Vision Diagnostics			
	HP Power Manager			
	McAfee Total Protection Anti-Virus with 60 day trial Subscription	Computrace Enabler for Desktops (select countries)**		
	Roxio Creater Business (select models)	SRS Premium Sound Software for HP Thin USB Powered Speakers (select models)		
	Firefox-HP Virtual Browser	Corel WinDVD (select models)		
	* Requires Broadcom NetXtreme Gigabit Ethernet Pl ** Requires HP LoJack Pro for ProtectTools for full fu subscription sold separately.			
Value-added Software	HP Client Automation – Starter Edition	HP Client Catalog for Microsoft SMS		
(available for free download from the Web http://www.hp.com/go/ easydeploy)	HP Client Manager from Symantec	HP Systems Software Manager		
	HP SoftPaq Download Manager	HP Disk Sanitizer, External Edition		



Standard Features and Configurable Components (availability may vary by country)

N/A

20.5 lb (9.3 kg)

1739 cu in 28.79 lb (13.06 kg)

N/A

19.69 x 12.2 x 23.62 in

500 x 310 x 600 mm

Value-added Services and Features	HP Stable Platform Program Business-to-Business Portals HP Global Series Services * TPM module disabled where use is restricted b	Factory Express Deployment and Lifecycle Services TPM 1.2 Security chip* y law; for example, Russia.
Service and Support	on-site repair for terms up to 5 years. Response to telephone support Note ³ 24 x 7. Global coverage country and transferred to another non-restricted warranty and service offering. Some countries/rea Care Pack services see: http://www.hp.com/go/l NOTE 1: Terms and conditions may vary by count NOTE 2: On-site service may be provided pursu HP third-party provider, and is not available in care based on commercially reasonable best effort an NOTE 3: Technical telephone support applies of	e Note ² ensures that any product purchased in one country will remain fully covered under the original gions do not offer one year onsite and labor. For HP pokuptool. http://certain.restrictions and exclusions apply. ant to a service contract between HP and an authorized ertain countries. Global service response times are
	Microtower	Small Form Factor
Chassis Dimensions (H x W x D)	14.85 x 6.95 x 16.96 in 377.2 x 176.5 x 430.8 mm	3.95 x 13.30 x 14.90 in 100.3 x 337.8 x 378.5

100.3 x 337.8 x 378.5 1.05 x 6.95 x 7.83 in (26.75 x 176.46 x 198.87 mm)

> 16.0 lb (7.26 kg) 941.63 cu in 26.70 lb (12.11 kg) 77.1 lb (35 kg)

9.72 x 19.68 x 22.67 in 246.9 x 499.9 x 575.8 mm

* Configured with 1 hard drive, 1 optical drive, no diskette drive, and no PCI card.

Power Supply	320W power supply – active PFC	240W power supply – active PFC
Energy Efficient Power Supply	320W 89% efficient power supply – active PFC	240W 89% efficient power supply – active PFC

Optional Tower Stand

Dimensions

(H x W x D) System weight*

System volume

Shipping weight* Maximum supported

weight (desktop orientation)

 $(H \times W \times D)$

Shipping box dimensions

USB 2.0 Serial Parallel PS/2 Video DVI output 10 (4 front, 6 rear) 1 standard with 2nd optional 1 optional 1 keyboard, 1 mouse analog for integrated graphics available via HP DisplayPort to DVI-D Adapter



Standard Features and Configurable Components (availability may vary by country) Support for Multi-Monitor 1 Standard DisplayPort and 1 Standard VGA Audio Integrated High Definition audio with internal speaker Front – mic and headphone Rear – input (supports microphone or line input), line out Integrated Intel 82567LM Gigabit Network Connection Ethernet NIC (RJ-45) MT SFF Chipset Intel Q43 Express chipset Х Х Intel Celeron Processors: Processor and Speed* One of the following Intel Celeron 450 Processor (2.2-GHz, 512K L2 cache, 800-MHz FSB) Х Х Intel Celeron Dual-Core Processors: Intel Celeron E3200 Processor (2.4-GHz, 2 MB L2 cache, 800-MHz FSB) Х Х Intel Celeron E3300 Processor (2.5-GHz, 2 MB L2 cache, 800-MHz FSB) Х Х Intel Pentium Dual-Core Processors: Intel Pentium dual-core E5300 Processor (2.6-GHz, 2MB L2 cache, 800-MHz FSB) Х Х Intel Pentium dual-core E5400 Processor (2.70-GHz, 2MB L2 cache, 800-MHz FSB) Х Х χ Intel Pentium dual-core E6300 Processor (2.80-GHz, 2MB L2 cache, 800-MHz FSB) Х Intel Core 2 Duo Processors: Intel Core 2 Duo E7500 Processor (2.93-GHz, 3 MB L2 cache, 1066-MHz FSB) Х Х Intel Core 2 Duo E7600 Processor (3.06-GHz, 3 MB L2 cache, 1066-MHz FSB) Х Х Intel Core 2 Duo E8400 Processor (3.0-GHz, 6 MB L2 cache, 1333-MHz FSB) Х Х Х Х Intel Core 2 Duo E8500 Processor (3.16-GHz, 6 MB L2 cache, 1333-MHz FSB) Intel Core 2 Duo E8600 Processor (3.33-GHz, 6 MB L2 cache, 1333-MHz FSB) Х Х Intel Core 2 Quad Processors: Intel Core 2 Quad Q8400 Processor (2.66-GHz, 4 MB L2 cache, 1333-MHz FSB) Х Х Х Intel Core 2 Quad Q9400 Processor (2.66-GHz, 6 MB L2 cache, 1333-MHz FSB) Х Intel Core 2 Quad Q9550 Processor (2.83-GHz, 12 MB L2 cache, 1333-MHz FSB) Х Х

* Intel processor numbers are not a measure of performance. Processor numbers differentiate features within each processor family, not across different processor families.

Intel Core 2 Quad Q9650 Processor (3.0-GHz, 12 MB L2 cache, 1333-MHz FSB)



Х

Х

Standard Features and Configurable Components (availability may vary by country)

Memory Supports un-buffered non-ECC DDR3 SDRAM The Intel Q43 Express chipset supports un-buffered non-ECC DDR3 SDRAM (synchronous dynamic random access memory) of up to 16GB total memory, and at a frequency of up to 1066MHz. NOTE: 1066MHz system memory frequency of operation requires at least PC3-8500 (DDR3-1066) memory type for all populated memory modules, and an Intel processor with FSB (front side bus) of at least 1066MHz. System Memory upgrades are accomplished by adding DDR3 SDRAM module(s) to empty DIMM slots on the System Board. CAUTION: Voltage is supplied to the memory modules whenever the computer is connected to an active AC outlet. Adding or removing memory modules while voltage is present may cause irreparable damage to the memory modules or system board. The computer must be shut down with the AC power removed (disconnect AC power cord at rear chassis or at AC outlet) prior to adding or removing SDRAM modules. HP recommends dual-channel symmetric configurations for the best memory performance. For best performance, add the same amount of total memory to each channel and do not inter-mix memory module speeds. For dual-channel symmetric performance, the total amount of memory in each channel must be equal. If memory module speeds are inter-mixed, the memory operating frequency will default to the slowest speed.

Microtower and Small Form Factor

Maximum Memory*

Supports up to 16GB of un-buffered non-ECC DDR3 SDRAM.

Slot 1 is black and must always be populated. Not all possible memory configurations are represented in the table below.

NOTE: For systems configured with more than 3GB of memory and a 32-bit operating system, all memory may not be available to the OS due to system resource requirements. Addressing memory above 4GB requires a 64-bit operating system.



Standard Features and Configurable Components (availability may vary by country)

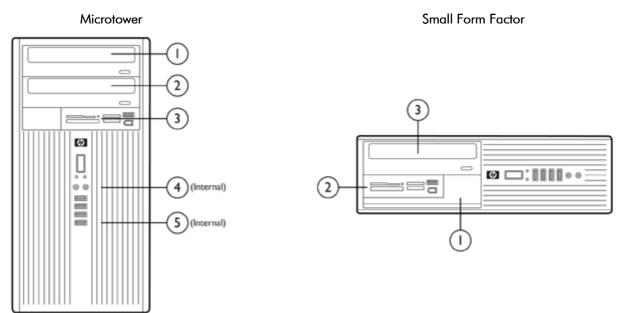
Total Memory	DIMM Slot Population				
	Channel A Channel B				
	1 (black)	2 (white)	3 (white)	4 (white)	
1-GB	1GB				
(Single Channel)					
2-GB	1GB		1GB		
(Dual Channel Symmetric)					
3-GB	2GB		1GB		
(Dual Channel					
Asymmetric)					
4-GB	2GB		2GB		
(Dual Channel Symmetric)					
4-GB	1GB	1GB	1GB	1GB	
(Dual Channel Symmetric)					
8-GB	2GB	2GB	2GB	2GB	
(Dual Channel Symmetric)					
16-GB maximum	4GB	4GB	4GB	4GB	
(Dual Channel Symmetric)					

* The Intel Q43 Express chipset includes an integrated Management Engine (ME) micro-controller, which requires system memory to support manageability functions. If the system memory configuration is single-channel or dual-channel asymmetric, 16MB of system memory is pre-allocated for the ME at system startup. If the memory configuration is dual-channel symmetric, 32 MB of memory is pre-allocated for the ME at system startup. This pre-allocated memory is not available to the operating system, just as pre-allocated video memory is not available.

Expandability	Microtower	Small Form Factor
PCI slots	1 full-height	1 low-profile
Max power per slot	35W	35W
PCle x1 slot	2	2
Max power per slot	10W	10W
PCle x16 slot (also functions as SDVO/ADD2 slot)	1 full-height	1 low-profile
Max power per slot	75W	35W
External Bays		
3.5"	1	1
5.25"	2	1
IDE		
Internal 3.5" HDD Bays	2	1
Hard Drive Controller (SATA) Supported	SATA	SATA
Hard Drive Interfaces Supported	SATA 3.0Gb/s	SATA 3.0Gb/s



Standard Features and Configurable Components (availability may vary by country)



Storage – Drive Support							
	Microtower			Small Form Factor			
	Media Card Reader or Pocket Media Drive (optional)	5.25" Serial ATA Devices	3.5" Serial ATA Devices	Media Card Reader or Pocket Media Drive (optional)	5.25" Serial ATA Devices	3.5" Serial ATA Devices	
Quantity Supported	1	2	2	1	1	2	
Position Supported	3	1,2	3,4,5	2	1	2,3	
Controller	USB/Diskette	SATA	SATA	USB/Diskette	SATA	SATA	

NOTE: The SATA port labeled SATA3 on the system board can be enabled by the BIOS as an eSATA port. Using it for an eSATA drive will require a separately purchased cable with an eSATA connector.



Standard Features and Configurable Components (availability may vary by country)

		MT	SFF
Hard Drive	160-GB SATA 3.0-Gb/s Hard Drive (8MB Cache, 7200 RPM, NCQ, Smart IV)	Х	Х
One or two of the	250-GB SATA 3.0-Gb/s Hard Drive (8MB Cache, 7200 RPM, NCQ, Smart IV)	Х	Х
following	320-GB SATA 3.0-Gb/s Hard Drive (8MB Cache, 7200 RPM, NCQ, Smart IV)	Х	Х
	500-GB SATA 3.0-Gb/s Hard Drive (16MB Cache, 7200 RPM, NCQ, Smart IV)	Х	Х
	80-GB SATA 3.0-Gb/s Hard Drive (16MB Cache,10,000 RPM, NCQ, Smart III)	Х	Х
	160-GB SATA 3.0-Gb/s Hard Drive (16MB Cache, 10,000 RPM, NCQ, Smart III)	Х	Х
	3.5" Removable 160-GB SATA 3.0 Gb/s Hard Drive (8MB Cache, 7200 RPM, NCQ, Smart IV)	Х	Х
	3.5" Removable 250-GB SATA 3.0 Gb/s Hard Drive (8MB Cache, 7200 RPM, NCQ, Smart IV)	Х	Х
	3.5" Removable 500-GB SATA 3.0 Gb/s Hard Drive (8MB Cache, 7200 RPM, NCQ, Smart IV)	Х	Х
	2 nd hard drive, 160-GB SATA 3.0-Gb/s Hard Drive (8MB Cache, 7200 RPM, NCQ, Smart IV)	Х	Х
	2 nd hard drive, 250-GB SATA 3.0-Gb/s Hard Drive (8MB Cache, 7200 RPM, NCQ, Smart IV)	Х	Х
	2 nd hard drive, 320-GB SATA 3.0-Gb/s Hard Drive (8MB Cache, 7200 RPM, NCQ, Smart IV)	Х	Х
	2 nd hard drive, 500-GB SATA 3.0-Gb/s Hard Drive (16MB Cache, 7200 RPM, NCQ, Smart IV)	Х	Х
	2 nd hard drive, 80-GB SATA 3.0-Gb/s Hard Drive (16MB Cache,10,000 RPM, NCQ, Smart III)	Х	Х
	2 nd hard drive,160-GB SATA 3.0-Gb/s Hard Drive (16MB Cache, 10,000 RPM, NCQ, Smart III)	Х	Х
	NOTE: NCQ functionality requires a user set-up BIOS setting.		
Solid State Drive	64-GB Solid State Drive	Х	Х
Removable Storage -	Pocket Media Drive		
One or more of the	250GB Pocket Media Drive	Х	Х
following depending on	Media Reader		
form factor (see Storage - Drive Support section	HP 22-in-1 Media Card Reader (USB connection on the system board)	Х	Х
above)	HP 22-in1 (with 1394) Media Card Reader (USB connection on the system board)	Х	Х
	Optical Drives		
	SATA DVD-ROM Drive	Х	Х
	SATA SuperMulti LightScribe DVD Writer Drive	Х	Х
	SATA Blu-ray Writer	Х	Х



Security	TPM 1.2 Embedded Security Chip*	Х	.,
		~ ~	Х
	HP Desktop Security lock kit (lock and cable)	Х	Х
	Security cable with Kensington lock	Х	Х
	HP Chassis Security Kit	Х	Х
	Optional HP ProtectTools 5.0 security software suite	Х	Х
	Optional LoJack Pro tracking and tracing subscription	Х	Х
	Optional USB Port Disable at factory (user configurable via BIOS)	Х	Х
	* TPM module disabled where use is restricted by law; for example, Russia.		
NIC	Intel 82567LM Gigabit Network Connection (integrated on system board)	Х	X
	Broadcom NetXtreme Gigabit Ethernet Plus PCIe NIC	Х	Х
	Broadcom NetXtreme Gigabit Ethernet Plus (DASH 1.1) PCIe NIC Card	Х	Х
	(with cable for internal USB header)		
	Intel Gigabit CT Desktop NIC	Х	X
Wireless	HP 802.11 b/g/n Wireless PCIe x1 card (full height bracket)	Х	
	HP 802.11 b/g/n Wireless PCIe x1 card (low profile bracket)		Х
Modem	LSI PCIe x1 56K International SoftModem	Х	Х
Graphics	Integrated Intel Graphics Media Accelerator 4500	Х	Х
	ATI Radeon HD 4650 (1 GB DH) PCIe x16 Graphics Card	Х	
	ATI Radeon HD 4550 Dual Head PCIe x16 Graphics Card	Х	Х
	NVIDIA Quadro NVS 290 PCIe x1 Graphics Card	Х	Х
	NVIDIA Quadro NVS 290 (256MB DH) PCIe x16 Graphics Card	Х	Х
	NVIDIA Quadro NVS 295 (256MB DH) PCIe x16 Graphics Card	Х	Х
	NVIDIA GeForce 310 DP PCIe x16 Graphics Card	Х	Х
	HP ADD2 SDVO PCIe DVI-D adapter	Х	Х
	HP DisplayPort to VGA Adapter	Х	Х
	HP DisplayPort to DVI-D Adapter	Х	Х
Audio	Integrated High Definition audio with Realtek ALC261 codec (all ports are stereo)	Х	X
	Microphone and Headphone front ports*	Х	Х
	Line-out and Line-In rear ports*	Х	Х
	Multistreaming capable*	Х	Х
	Internal Speaker	Х	Х
	HP Thin USB Powered Speakers (optional)	Х	Х
	* Re-taskable ports; see technical specifications page 21.		



Standard Features and Configurable Components (availability may vary by country)

Input Devices	Keyboard - One of the following		
	HP PS/2 Standard Keyboard	Х	Х
	HP USB Standard Keyboard	Х	Х
	HP Smartcard Keyboard	Х	Х
	HP USB PS/2 Washable Keyboard	Х	Х
	HP USB Mini Keyboard	Х	Х
	Mouse - One of the following		
	USB 2-Button Laser Mouse	Х	Х
	PS/2 2-Button Optical Scroll Mouse	Х	Х
	USB 2-Button Optical Scroll Mouse	Х	Х
Miscellaneous	2 nd serial port adapter	Х	
	2 nd serial port adapter (low profile)		Х
	Parallel port adapter	Х	Х
	HP FireWire / IEEE 1394 Adapter	Х	Х
	Tower stand		Х



After-Market Options (availability may vary by region)

		MT	SFF	Part Number
Communications	Wireless LAN			
	HP 802.11 b/g/n Wireless PCle x1 card	Х	Х	FH971AA
	NICs			
	Broadcom NetXtreme Gigabit Ethernet Plus (DASH 1.1) PCIe NIC (with cable for internal USB header)	Х	Х	EA833AA
	Intel Gigabit CT Desktop NIC	Х	Х	FH969AA
	Modem			
	LSI PCIe x1 56K International SoftModem	Х	Х	FH970AA
Graphics	Single head solutions			
	HP ADD2 SDVO PCIe DVI-D Adapter	Х	Х	DY674A
	Multi head solutions			
	ATI Radeon HD 4550 (256MB DH) PCIe x16 Card	Х	Х	AT042AA
	ATI Radeon HD 4650 (1 GB DH) PCle x16 Graphics Card	Х		VN566AA
	HP DisplayPort to VGA Adapter	Х	Х	AS615AA
	HP DisplayPort to DVI-D Adapter	Х	Х	FH973AA
	NVIDIA Quadro NVS 290 (256MB DH) PCIe x1 Graphics Card	Х	Х	KN586AA
	NVIDIA Quadro NVS 290 (256MB DH) PCIe x16 Graphics Card	Х	Х	KG748AA
	NVIDIA Quadro NVS 295 (256MB DH) PCIe x16 Graphics Card	Х	Х	FY943AA
	NVIDIA GeForce 310 DP PCIe x16 Graphics Card	Х	Х	VG885AA
Hard Drives	Serial ATA Hard Drives			
	HP 160-GB SATA 3.0-Gb/s 7200 rpm Hard Drive	Х	Х	PY277AA
	HP 250-GB SATA 3.0-Gb/s 7200 rpm Hard Drive	Х	Х	PY278AA
	HP 320-GB SATA 3.0-Gb/s 7200 rpm Hard Drive	Х	Х	FH963AA
	HP 500-GB SATA 3.0-Gb/s 7200 rpm Hard Drive	Х	Х	KW347AA
	HP 80-GB SATA 3.0-Gb/s 10,000 rpm Hard Drive	Х	Х	EM172AA
	HP 160-GB SATA 3.0-Gb/s 10,000 rpm Hard Drive	Х	Х	EW222AA
	HP Removable SATA Hard Drive Enclosure (Frame & Carrier)	Х	Х	RY102AA
	HP Removable SATA Hard Drive Enclosure (Carrier Only)	Х	Х	RY103AA



After-Market Option	ns (availability may vary by region)			
Input/Output Devices	HP PS/2 Standard Keyboard	Х	Х	DT527A
	HP USB Standard Keyboard	Х	Х	DT528A
	HP USB Smartcard Keyboard	Х	Х	ED707AA
	HP USB Gray Standard Keyboard	Х	Х	DT529A
	HP USB PS/2 Washable Keyboard	Х	Х	VF097AA
	HP USB Mini Keyboard	Х	Х	AS601AA
	HP 2.4 GHz Wireless Keyboard and Mouse	Х	Х	NB896AA
	HP USB Laser Mouse	Х	Х	GW405AA
	HP PS/2 2-Button Optical Scroll Mouse	Х	Х	EY703AA
	HP USB 2-Button Optical Scroll Mouse	Х	Х	DC172B
Memory (DIMMs)	PC3-10600 (DDR3, 1333MHz) DIMMs Non-ECC			
	HP 4-GB PC3-10600 (DDR3 1333 MHz) DIMM	Х	Х	VH638AA
	HP 2-GB PC3-10600 (DDR3 1333MHz) DIMM	Х	Х	AT024AA
	HP 1-GB PC3-10600 (DDR3 1333 MHz) DIMM	Х	Х	AT023AA
Monitors	All HP monitors are supported that accept a graphics output provided by this PC. The LP3065 monitor can be supported by installing a graphics card that supports a dual-link DVI-D output.			
Multimedia	HP Thin USB Powered Speakers	Х	Х	KU901AV
Optical Drives	DVD-ROM Drive			
•	HP SATA DVD-ROM Drive	Х	Х	AH047AA
	DVD Writer			
	SATA Blu-ray Writer	Х	Х	AR481AA
	HP SATA SuperMulti LightScribe DVD Writer Drive	Х	Х	GF343AA
Removable Storage	Removable Drives			
-	HP 250GB Pocket Media Drive	Х	Х	FE477AA
	Multimedia			
	HP 22-in-1 Media Card Reader	Х	Х	FX273AA
	HP 22-in-1 (with 1394) Media Card Reader	Х	Х	KN518AA



After-Market Options (availability may vary by region)

Security	Kensington lock	Х	Х	PC766A
	HP Business PC Security Lock	Х	Х	PV606AA
	HP Chassis Security Kit	Х	Х	AR639AA
	HP ProtectTools 5.0 Client Security Software including HP ProtectTools Security Manager Credential Manager for HP ProtectTools Device Access Manager for HP ProtectTools Drive Encryption for HP ProtectTools Embedded Security for HP ProtectTools Java Card Security for HP ProtectTools LoJackPro for HP ProtectTools Privacy Manager for HP ProtectTools File Sanitizer for HP ProtectTools	Х	Х	TBD
	HP 2009 Wall Mount/Security Sleeve		Х	TBD
Manageability	HP Client Configuration Manager, Premium Edition	Х	Х	T3488AA (use T3489AA for 1000 licenses)
	Broadcom NetXtreme Gigabit Ethernet Plus (DASH 1.1) PCIe NIC (with cable for internal USB header)	Х	Х	EA833AA
Brackets/Stands	HP 2009 Small Form Factor Tower Stand		Х	VN569AA
Miscellaneous	HP Serial Port Adapter Kit	Х	Х	PA716A
Accessories	HP Parallel Port Adapter Kit	Х	Х	KD061AA
	HP FireWire / IEEE 1394 Adapter	Х	Х	PA997A
NOTE: This document	t is a Worldwide document. All features are not available in all regions.			



Technical Specifications

Unit Environment and Operating Conditions	Microtower	Small Form Factor
General Unit Operating Guidelines		
 operated within the specified operatin Leave a 10.2 cm (4 in) clearance on Never restrict airflow into the comput Do not stack computers on top of eac circulated or preheated air. Occasionally clean the air vents on the matter can block the vents and limit the 	all vented sides of the computer to permit the er by blocking any vents or air intakes. ch other or place computers so near each oth ne front, back, and any other vented side of t he airflow. nin a separate enclosure, intake and exhaust	e required airflow. her that they are subject to each other's re- he computer. Lint, dust and other foreign
Temperature Range	Operating: 50° to 9 Non-operating: -22° to	25° F (10° to 35° C)* 5 140° F(-30° to 60° C)
Relative Humidity Operating: 10% to 90% (non-condensing at ambient) Non-operating: 5% to 95% (non-condensing at ambient)		e ,
Maximum Altitude (unpressurized)		000 ft (3048 m) 0,000 ft (9144 m)

* Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.

	Microtower		Small Form Factor	
Power Supply	320-watt BTX power supply - Active PFC	320-watt 89% efficient* BTX power supply - Active PFC	240-watt BTX power supply - Active PFC	240-watt 89% efficient* BTX power supply - Active PFC
Operating Voltage Range	100-240VAC	100-240VAC	100-240VAC	100-240VAC
Rated Voltage Range	115V/230V	115V/230V	115V/230V	115V/230V
Rated Line Frequency	50/60 Hz	50/60 Hz	50/60 Hz	50/60 Hz
Operating Line Frequency Range	47-63 Hz	47-63 Hz	47-63 Hz	47-63 Hz
Rated Input Current	5.5A	5.5A	4A	4A
Heat Dissipation (NEED TO UPDATE)	Typical 315 btu/hr (79 kg-cal/hr) Maximum 1575 btu/hr (397 kg-cal/hr)	Typical 270 btu/hr (68 kg-cal/hr) Maximum 1280 btu/hr (322 kg-cal/hr)	Typical 315 btu/hr (79 kg-cal/hr) Maximum 1260 btu/hr (317 kg-cal/hr)	Typical 270 btu/hr (68 kg-cal/hr) Maximum 1025 btu/hr (258 kg-cal/hr)
Power Supply Fan	Variable speed fan	Variable speed fan	Variable speed fan	Variable speed fan
ENERGY STAR Compliant		Х		Х
FEMP Standby Power Compliant (<1W in S5 - Power Off)**	Х	Х	Х	Х
Power Consumption in ENERGY STAR Mode - Suspend to RAM (S3) (Instantly Available PC)	<4W	<3W	<4W	<3W



Technical Specifications

* Energy efficient power supply is a requirement for ENERGY STAR qualification in conjunction with a select range of processors and modules

** Power consumption in the Off/Apparent Off mode is measured and reported with the network interface controller "Wake on LAN" feature disabled in F10 Setup (default is "enabled").

ROM BIOS Information

Key features of the HP BIOS include:

- Deployment and manageability HP BIOS provides several technologies that help integrate the HP Business desktop computer into the enterprise, such as PXE, remote configuration, remote control, and F10 Setup support for 12 languages.
- Stability HP BIOS supports the HP stable product roadmap by releasing only critical BIOS changes to the factory and advanced change notification.
- Security HP BIOS offers a robust and flexible set of security features to help the system administrator secure their systems from removal of sensitive data, and help prevent access by unauthorized users. Ability to disable USB ports.
- Tracking and tracing capabilities in case of theft available in select countries (subscription sold separately).
- Thermal and power management The HP BIOS provides and enables thermal and power management technologies to assist in operating the HP Business Desktop computer in any enterprise environment.
- Serviceability HP BIOS provides diagnostic and detailed service information.
- Upgrades and recovery HP BIOS provides numerous ways to upgrade HP Business Desktop computers, including BIOS updates from within DOS (Flashlite), BIOS updates from within Windows (HPQFlash, SSM), HP Client Manager, and fail-safe recovery. In addition, the HP Business Desktop BIOS Utilities tool enables replicated BIOS setup throughout the Enterprise; it is available from within the BIOS software and from the support website.

Additional HP BIOS Features

- Administrator password Also known as the setup password, this helps prevent unauthorized changes to the system configuration. If the administrator password is not known, the BIOS version cannot be changed and changes cannot be made to BIOS settings using F10 setup or under the OS.
- Advanced Configuration and Power Interface (ACPI) Represents a significant innovation in power and configuration
 management, allowing operating systems and applications to manage power based on activity and usage. Provides power
 conservation features under Windows XP.
- Mute internal speaker
- Disable USB ports

Other Features	Description	
ACPI-Ready Hardware	Advanced Configuration and Power Management Interface (ACPI).	
	 Allows the system to wake from a low power mode. Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system. 	
SMBIOS Ver. 2.6	System Management BIOS, previously known as DMI BIOS, for system management information	
Wired for Management Support	Intel-driven, industry-wide initiative to make Intel architecture-based PCs, servers and mobile computers more inherently manageable right out of the box and over the network	
Dual-State Power Button	Power button acts as both an on/off button and suspend-to-sleep button	



Technical Specifications

Serviceability Features of System			
Dual Color Power LED on Front of Compu	uter (Indicates Normal Operations and Fault (Conditions)	
Diagnostic LED Explanation Table	Number of 1-second red LED blinks followed by 2-second pause, then repeats: 2-processor thermal protection activated 3-processor not installed 4-power supply failure 5-memory error 6-video error 7-PCA failure (ROM detected failure prior to video)		
System/Emergency ROM	 8-invalid ROM, bootblock recover mode Flash ROM 	CMOS Battery Holder for easy Replacement	
Flash Recovery with Video	• 5 Aux Power LED on System PCA	 Processor ZIF Socket for easy Upgrade 	
 Over-Temp Warning on Screen (Requires IM Agents) 	Clear Password Jumper	DIMM Connectors for easy Upgrade	
Restore CD	Clear CMOS Switch	 NIC LEDs (integrated) (Green & Amber) 	

Serviceability Features of Chassis			
 Dual Color Power and HD LED – To Indicate Normal Operations and Fault Conditions 	 Color coordinated cables and connectors 	 Tool-less Hood Removal (thumbscrews for Microtower, spring- loaded latch for Small Form Factor) 	
Front power switch	 System memory can be upgraded on Microtower without removing any internal components 	 Tool-less Hard Drive, CD & Diskette Removal 	
Additional Features	Description		
Towerable	Small Form Factor can be oriented as a towe	er (in addition to desktop orientation)	
Drive Self Tests (DPS)	 Drive Protection System A diagnostic hard drive self test. It scans critical physical components and every sector of the hard drive for physical faults and then reports any faults to the user. Running independently of the operating system, it can be accessed through a Windows-based diagnostics utility or through the computer's setup procedure. It 		
DPS Access through F10 Setup during Boot			
SMART IV Technology* (Self-Monitoring, Analysis and Reporting Technology)	Allows hard drives to monitor their own health and to raise flags if imminent failures were predicted		
	 parameters such as re-allocated sector count By avoiding actual hard drive failures, against unplanned user downtime and 	l potential data loss from hard drive failure	
Intel® Standard Manageability	All models feature Intel Standard Manageabi	llity technology including the tollowing*:	



Technical Specifications

	 Supports industry standards including DASH 1.1 and WSMAN Enables IT to manage and secure PCs even if they are off or the OS is inoperable. Remotely manage power states, boot to a diagnostic image, edit the PC BIOS, and inventory software and hardware. Hardware-level filtering can automatically remove an infected PC from the network while still keeping a connection to the management console for remote remediation. 	
computer system to have an Intel AMT-enab and a corporate network connection. Setup	ude features of Intel Active Management Technology (Intel AMT). Intel AMT requires the led chipset, network hardware and software, as well as connection with a power source requires configuration by the purchaser and may require scripting with the management ecurity frameworks to enable certain functionality. For more information, see ogy/intel-amt/.	
DASH 1.1 support (Desktop and Mobile A standards initiative for representing out-of-band management capability for construction of the system of the systems. It is a secure, web-services based successor to ASF.		
,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	Industry-standard specification for network alerting in operating system-absent environments	



Technical Specifications - Audio

High Definition Audio	Type High Definition Stereo Codec	Integrated Yes - 4-channel Realtek ALC261 codec
	Audio Jacks	Front microphone-In (150-K ohm Input Impedance)
		Rear Line-In/Microphone input (150-K ohm Input Impedance, function is configurable by audio driver)
		Rear Line-Out* (190 ohms Output Impedance, expects at least a 10-K ohm load)
		Front Headphone-Out (0.5 Ohm Output Impedance, expects at least a 32 ohm load)
	NOTES:	

Internal Speaker Amplifier is for Internal Speaker only. External Speakers need to be powered externally.

The rear input port can function as a Line-In or Microphone-In jack.

The front Microphone jack is retaskable to support headphones. When functioning as a headphone jack the same audio stream will be sent to both front jacks.

The front Microphone jack is also retaskable to function as a Line-in jack.

The Realtek Control Panel software required to reassign audio ports is preloaded but must be installed by the customer before these functions can be performed.

Multistreaming Capable	Multistreaming can be enabled in the Realtek control panel to allow independent audio streams to be sent to/from the front and rear jacks.
Sampling	8 kHz - 192 kHz
Wavetable Syntheses (software)	Yes - Uses OS soft wavetable
Analog Audio	Yes
Number of Channels on Line-Out (mono/stereo)	Stereo (Left & Right channels)
Internal Audio Speaker Power Rating	1.5 W
Internal Speaker	Yes; ability to mute internal speaker through F10 Setup
External Speaker Jack (Line-Out)	Yes



Integrated Intel 82567LM	Connector	RJ-45
Gigabit Network	Controller	Intel 82567LM Gigabit platform LAN Connect Networking Controller
Connection	Memory	Integrated 96KbB on chip buffer memory
	, Data rates supported	10/100/1000 Mbps
	Compliance	IEEE 802.1P, 802.1Q, 802.2, 802.3, 802.3 ab and 802.3u compliant
	Bus architecture	GLCI, LCI interface. Intel specific MAC to PHY interface
	Data transfer mode	At gigabit GLCI (802.3 serdes) is for Data, LCI (parallel bus)for MDIO, at 10/100 LCI for both data and MDIO, GLCI is idle.
	Power requirement	Require 3.3Vaux,1.8V and 1.0V or just 3.3V with integrated regulators Power consumption 1.16 Watts for 82566, whole LOM 2.53 Watts
	Boot ROM support	Yes
	Network transfer mode	Full-duplex
		Half-duplex (not available for the 1000BASE-T transceiver)
	Network transfer rate	10BASE-T (half-duplex) 10 Mbps
		10BASE-T (full-duplex) 20 Mbps
		100BASE-TX (half-duplex) 100 Mbps
		100BASE-TX (full-duplex) 200 Mbps
		1000BASE-T (full-duplex) 2000 Mbps
	Environmental	Operating temperature 32° to 131° F (0° to 55° C)
		To 70° C for external regulator
		Operating humidity 85% at 131° F (55° C)
	Management capabilities	WOL, auto MDI crossover, PXE, Muti-port teaming, RSS, Advanced cable diagnostic.
	Alerting	ASF 2.0 support, AMT 3.0 support
Intel Gigabit CT Desktop	Connector	RJ-45
NIC	Controller	Intel WG82574L Gigabit Ethernet Controller
	Memory	Integrated Dual 48K configurable transmit receive FIFO Buffers
	Data rates supported	10/100/1000 Mbps
	Compliance	IEEE 802.1P, 802,1Q, 802.2, 802.3, 802.3AB and 802.3u compliant, 802.3x flow control
	Bus architecture	PCI-E 1.0a
	Data path width	X1, 250 MB/s, Bi-directional interface
	Data transfer mode	Bus-master DMA
	Hardware certifications	FCC, B, CE, TUV- cTUVus Mark Canada and United States, TUV- GS Mark for European Union
	Power requirement	Aux 3.3V, 3.0 Watts in 1000base-T and 2.0 Watts in 100Base-T
	Boot ROM support	Yes



Network transfer rate	10BASE-T (half-duplex) 10 Mbps		
	10BASE-T (full-duplex) 20 Mbps		
	100BASE-TX (half-duplex)	100 Mbps	
	100BASE-TX (full-duplex) 200 Mbps		
	1000BASE-T (full-duplex) 2000 Mbps		
Environmental	Operating temperature	32° to 131°F (0° to 55° C)	
	Operating humidity	85% at 131° F (55° C)	
Dimensions	4.75 x 2.25 x 0.8 in (12.1	x 5.7 x 2.0 cm)	
Operating system driver support	Windows Vista Business 64*, Windows Vista Business 32*, Windows Vista Home Basic 32*, Windows XP Professional or Windows XP Home 32*. No driver is required for this device. Native support is provided by the operating system. Red Hat Linux 7.2, Linux 7.3 and Red Hat Enterprise Linux 3		
	* Certain Windows Vista product features require advanced or additional hardware. Windows Vista Upgrade Advisor can help you determine which features of Windows Vista will run on your computer. To download the tool, visit: http://www.windowsvista.com/upgradeadvisor. For Windows Vista system requirements, visit: http://www.windowsvista.com/systemrequirements.		
Management capabilities	s WOL, PXE, DMI, WFM 2.0		

Broadcom NetXtreme	Connector	RJ-45
Gigabit Ethernet Plus	Controller	Broadcom 5761 PCI-Express LAN Controller
PCIe NIC Card	Memory	8 MB NVRAM serial Flash
	Data rates supported	10/100/1000 Mbps
	Compliance	IEEE 802.1P, 802.1Q, 802.2, 802.3, 802.3AB, 802.3u, and 802.3x
	Bus architecture	PCI-E
	Data path width	Single channel, PCI-E
	Data transfer mode	Bus-master DMA
	Hardware certifications	FCC class B, Canada and US NRTL Mark, C-Tick for Australia, BSMI for Taiwan, VCCI for Japan, MIC for Korea, GOST for Russia, UL listed (E212044), European Union Notice (CE 0682)
	Power requirement	1.8W @ 3.3V
	Boot ROM support	Yes
	Network transfer mode	Full-duplex
		Half-duplex (not available for the 1000BASE-T transceiver)
	Network transfer rate	10BASE-T (half-duplex) 10 Mbps
		10BASE-T (full-duplex) 20 Mbps
		100BASE-TX (half-duplex) 100 Mbps
		100BASE-TX (full-duplex) 200 Mbps
		1000BASE-T (full-duplex) 2000 Mbps (actual rate limited by PCI Bus)



Fechnical Specificatio	ns - Communications	5				
	Environmental	Operating temperature	32° to 131°F (0° to 55° C)			
		Operating humidity	131° F (55° C) with 5% to humidity	95% non-condensing		
	Dimensions	2.75 in x 4.13 in (7 cm x 1	0.5 cm), low profile compo	itible		
	Management capabilities	ACPI, WOL and DMI 2.0, I ASF2.0, DASH 1.0 and DA		om mgmt utility,		
HP 802.11b/g/n Wireless	Dimensions (L x H)	3.3 x 4.7 inches (8.5 x 12	cm)			
PCle x1 Card	Weight	0.08 pounds (40 g)				
	Controller	Ralink RT2790				
	System interface	PCIExpress x1				
	Network standard	802.11 b/g/n				
	Frequency band	2.400 - 2.497 GHz				
	Operating temperature	14° to 149°F, operating (-	10° to 65°C, operating)			
	Storage temperature	-40° to 176°F, non-operating (-40° to 80°C, non-operating)				
	Humidity	10-90% operating 5-95% non-operating				
	Operating voltage	3.3V +/- 9% 12V +/- 8%				
	Power consumption	Platform/WLAN Mode	Power Consumption			
		Maximum Power Consumption	10 Watts			
		Transmit Only	4 Watts maximum averaged power over 1 second			
		Transmit Packet or Active Scanning	1000 mA peak current for 100 microseconds or longer			
		Receive Only Mode or Idle without IEEE PSP mode enabled	3 Watts maximum average	ed over 1 second		
		Idle, with IEEE PSP mode enabled	1.0 Watts maximum avera	iged over 1 second		
		Transmit Disabled (turned off in software)	50 mW maximum, averag	ed over 1 second		
		Platform in S3 or S4 (power removed from Low Profile PCI Express Card)	5 mW maximum, averaged over 1 second			
	Output power	802.11b modes	802.11g modes	EWC modes		
	(approximately)	+19 dBm +/- 1.0 dB maximum	+17 dBm +/- 1.0 dB maximum	+17 dBm +/- 1.0 dB maximum (total power in all transmit chains)		
				,		
	Receive sensitivity	Mode	Data rate	Sensitivity		
	Receive sensitivity	Mode 802.11b	Data rate 1 Mbps	Sensitivity -94 dBm		



	802.11g	6 Mbps	-91 dBm
	802.11g	18 Mbps	-85 dBm
	802.11g	48 Mbps	-75 dBm
	802.11g	54 Mbps	-72 dBm
	EWC (2.4 GHz)	6.5 Mbps	-87 dBm
	EWC (2.4 GHz)	54 Mbps	-82 dBm
	EWC (2.4 GHz)	81 Mbps	-78 dBm
	EWC (2.4 GHz)	162 Mbps	-74 dBm
	EWC (2.4 GHz)	270 Mbps	-68 dBm
	EWC (2.4 GHz)	300 Mbps	-64 dBm
Data transfer rate	Data Rate (MCS)	Minimum Throughput	
	1 Mbps (802.11 b)	700 kbps	
	2 Mbps (802.11 b)	1.4 Mbps	
	5.5 Mbps (802.11 b)	3.5 Mbps	
	11 Mbps (802.11 b)	5.9 Mbps	
	12 Mbps (802.11 g)	6 Mbps	
	18 Mbps (802.11 g)	9 Mbps	
	24 Mbps (802.11 g)	12 Mbps	
	36 Mbps (802.11 g)	18 Mbps	
	48 Mbps (802.11 g)	21 Mbps	
	54 Mbps (802.11 g)	22.5 Mbps	
	6.5 Mbps (20 MHz EWC)	4.5 Mbps	
	13 Mbps (20 MHz EWC)	9 Mbps	
	19.5 Mbps (20 MHz	13.5 Mbps	
	EWC)	·	
	26 Mbps (20 MHz EWC)	18 Mbps	
	39 Mbps (20 MHz EWC)	27 Mbps	
	52 Mbps (20 MHz EWC)	36 Mbps	
	58.5 Mbps (20 MHz EWC)	40 Mbps	
	65 Mbps (20 MHz EWC)	45 Mbps	
	78 Mbps (20 MHz EWC)	54 Mbps	
	104 Mbps (20 MHz EWC)	72 Mbps	
	117 Mbps (20 MHz EWC)	81 Mbps	
	130 Mbps (20 MHz EWC)	91 Mbps	
	13.5 Mbps (40 MHz EWC)	8 Mbps	
	27 Mbps (40 MHz EWC)	16 Mbps	
	40.5 Mbps (40 MHz EWC)	24 Mbps	
	54 Mbps (40 MHz EWC)	32 Mbps	
	81 Mbps (40 MHz EWC)	48 Mbps	



reennear opeenneare		
		108 Mbps (40 MHz EWC) 64 Mbps
		121.5 Mbps (40 MHz 72 Mbps EWC)
		135 Mbps (40 MHz EWC) 81 Mbps
	Security	 IEEE and WiFi compliant 64 / 128 bit WEP encryption AES: CCM 802.1x authentication WPA: 802.1x. WPA-PSK and TKIP
		 WPA2 certification IEEE 802.11i
		 Cisco Certified Extensions, all versions through V5
	Antenna	HP part number 497792-001
	Certifications	Wi-Fi certified
	Certifications for use by country	United States, Canada, Peru, Taiwan
LSI PCle x1 56K	Data Transmission	Technology speeds: 56,000 Kbps maximum downstream data, controllerless
International SoftModem		NOTE: 56 Kbps technology refers to download speeds only and requires compatible modems at server sites. Other conditions may limit modem speed. FCC limitations allow a maximum of 53 Kbps during download transmissions.
	Data Speeds	(Upload only) 33,600/31,200/28,800/26,400/21,600/19,200/ 16,800/14,400/12,000/9,600/7,200/4,800/2,400/1,200/300
	Data Standards	ITU-T V.90, ITU-T, ITU-T V.34, V.44, V.42, V.42bis21, V.32bis, Bell 212A, and Bell 103
	Fax Speeds	14,400/12,000/9,600/7,200/4,800/2,400/1,200/300 b/s
	Fax Mode Capabilities	ITU-T T.31 class 1 FAX, V. 17, V.29, V.27ter, and V.21 Channel 2
	Error Correction and Data Compression	V.44, 42bis, V.42 and MNP2-5
	Power Management	PCI Bus Power Management Interface Specification (PCI-PM) Revision 1.2, Appendix A. DO, D3hot, and D3cold. Wake on Ring state when in D3cold. If the power management event (PME) feature is enabled in D3cold, a modem can wake the system via WAKE# (WAKEN) or beacon. Meets PCI Express 1.1 standard.
	Upgradeability	Driver upgradeable for future enhancements
	Video	ITU-T V.80 video ready interface
	Other	TIA/EIA 602 standard AT command set
		Integrated DTE interface with speeds of up to 115.2 Kbps, parallel 16550a UART-compatible interface
		Optional ring wakeup signal
	Operating Temperature	32° to 158° F (0° to 70° C)
	Operating Humidity	20% to 90%, non-condensing
	Power	Requires a 3.3-V auxiliary power rail on PCI express bus
		Uses only one PCI express load (i.e., one grant/request pair), one shared IRQ, one electrical load



Chipset	LSI SV92EX - Integrated PCI interface with 3.3-V tolerant buffers and CardBus support
Dimensions (L X H)	Complies with PCI express low profile specifications-6.7 x 2.3 in (17.0 x 5.8 cm) and supports high- and low-profile brackets
Connection	Single RJ-11 connector
Other Features	Digital line protection, call progress monitoring via on-board piezo device, support for high profile and low profile brackets, PnP ID support
Safety	UL recognized to UL 1950, 3 rd edition (U.S. and Canada); IEC 950 (TUV, NEMKO, DEMKO, SEMKO); CE Mark, EC 950 (TUV, NEMKO, DEMKO, SEMKO, CE mark
EMC	FCC Part 15, IC ES003, EN 55022, 3 rd edition, EN 55024, annex A, EN 61000-4-6, EN 61000-4-8
Telecom	FCC Part 68, IC-CS-03 (Canada); Worldwide PTT approvals Not available in Korea or the Republic of South Africa.
Other	The SV92EX device is packaged in a 32-pin micro leadless chip carrier (MLCC). The SV92EX is fully compliant with the PCI Express revision 1.1 specification. WHQL approved; ASPM compliant.



Technical Specifications - Graphics

Integrated Intel Graphics Media Accelerator 4500	3D/2D Controller VGA Controller DisplayPort Bus Type RAMDAC	Microsoft DirectX® 10 based with support for Pixel Shader 3.0 Integrated Integrated, Multimode capable; supports HDCP PCI Express™ x16 Integrated, 350 MHz
	Memory	Graphics memory is shared with system memory. Graphics memory usage varies depending on the amount of system memory installed, BIOS settings, operating system, and system load. 32 MB is pre-allocated for graphics use at system boot time. Additional memory can be allocated at boot time by the BIOS for PAVP (Protected Audio Video Playback) support for playback of protected video content. For Vista, use of PAVP heavy mode preallocates an additional 96MB.

Additional memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.

Windows XP Memory Usage:

Total System Memory	Pre-Allocated (MB)	DVMT (MB)
.5GB	32	128
1.0GB	32	512
1.5GB	32	768
2 GB & more	32	1024

Windows Vista Memory Usage:

(Assumes Management Engine , VT-d enabled and other memory allocated for other BIOS usage)

System	PAVP	Avail System	Total Avail GFX	Dedicated Video	System Video	Shared System
Memory	17.01	Memory	Memory	Memory	Memory	Memory
		(MB)	(MB)	(MB)	(MB	(MB)
1 GB	Lite	952	252	32	96	124
IGD	Heavy	856	294	122	6	166
2 GB	Lite	1976	764	32	96	636
	Heavy	1880	806	122	6	678
4 GB	Lite	4024	1759	32	96	1631
	Heavy	3928	1759	122	6	1631
6 GB	Lite	6072	1759	32	96	1631
	Heavy	5976	1759	122	6	1631
	Lite	8120	1759	32	96	1631
8 GB	Heavy	8024	1759	122	6	1631

Total Available GFX Memory: Total graphics memory available to the system as reported by the OS.

Dedicated Video Memory: Memory owned and locked for graphics use as reported



Technical Specifications - Graphics

by the OS. (Preallocated)

System Video Memory: System memory locked and dedicated for graphics use.

	Shared System Memory: Memory dynamically allocated for Graphics use
HW Video Decode	Hardware Accelerated decode for MPEG2 encrypted video; support for PAVP Lite (default) and Heavy (or Paranoid) modes
Maximum Color Depth	32 bits/pixel
Maximum Vertical Refresh Rate	85 Hz at up to 1920x1440, 75 Hz at 2048x1536. Varies with mode and configuration. See table below.
Multi-display Support	Dual monitor support facilitated via one VGA port and one DisplayPort integrated on the back plane of the system board and presented as part of the rear I/O set of interfaces. DVI supported via optional HP DisplayPort to DVI-D adapter.
Graphics/Video API Support	$\label{eq:microsoft} \mbox{Direct} X \mbox{$^{\top}$ 10, OpenGL $^{\top}$ 1.5 (OpenGL $^{\top}$ 2.0 available in a driver update)}$

Resolutions Supported

NOTE: Other resolutions may be available but are not recommended as the may not have been tested and qualified by HP.

	Maximum Re	fresh Rate (Hz)
Resolution	Analog Connection	Digital Connection
640x480	85	60
800x600	85	60
1024x768	85	60
1280x720	85	60
1280x1024	85	60
1440x900	75	60
1600x1200	85	60
1680x1050	75	60
1920x1080	85	60-R
1920x1200	85	60-R
1920x1440	85	N/A
2048x1536	75	N/A
2560x1600	N/A	60*

* Only supported when using a DisplayPort connection

NOTE: 60-R denotes reduced blanking timings are used on single-link DVI connections and may be used with other digital connections.

ATI Radeon HD 4650 (1
GB DH) PCle x16
Graphics Card (FH Only)

Bus type Maximum vertical refresh rate 85 Hz Display support Display max resolution Board display options

PCI Express (x16 lanes)

Integrated 400 MHz RAMDAC

2560 x 1600 digital, 2048 x 1536 analog

Supports two displays through any combination of two of the three output ports.



Technical Specifications - Graphics

Board configuration	Specification	Description
	Graphics Chip	RV730Pro
	Core clock	600 MHz
	Memory clock	500 MHz
	Frame buffer	1 GB DDR3, 128 bit wide
Maximum power	55 W	
Languages supported	24 languages: English, Arabic, Chinese Simplified, Chinese Traditional, Czechoslovakian, Danish, Dutch, Finnish, French, German, Greek, Hebrew, Hungarian, Italian, Japanese, Korean, Norwegian, Polish, Portuguese, Russian, Spanish, Swedish, Thai, Turkish	
Compliance standards	EMC Emissions: a) CISPR22: 1997/EN 55022:1998 - Class B - Limits and methods of measurement of radio disturbance characteristics of Information Technology Equipment EMC Immunity: CISPR 24:1997/EN 55024:1998 Information Technology Equipment	

CISPR 24:1997/EN 55024:1998 - Information Technology Equipment -Immunity Characteristics - Limits and Methods of Measurement.

ATI Radeon HD 4650 (! GB) PCle x16 Graphics Card display resolutions and refresh rates

NOTE: Other resolutions may be available but are not recommended as the may not have been tested and qualified by HP.

	Maximum Refresh Rate (Hz)	
Resolution	Analog Connection	Digital Connection
640x480	85	60
800x600	85	60
1024x768	85	60
1280x720	85	60
1280x1024	85	60
1440x900	75	60
1600x1200	85	60
1680x1050	75	60
1920x1080	85	60-R*
1920x1200	85	60-R
1920x1440	85	N/A
2048x1536	75	N/A
2560x1600	N/A	60**

* Max HDMI resolution is 1080p

** Only supported when using a dual-link DVI connection

NOTE: 60-R denotes reduced blanking timings are used on single-link DVI connections and may be used with other digital connections.

 ATI Radeon HD 4550 (256 MB DH) PCle x16 Graphics Card
 Bus type
 PCI Express (x16 lanes)

 Maximum vertical refresh rate Display support
 85 Hz

 Display max resolution
 1900 x 1200 digital, 2048 x 1536 analog



Technical Specifications - Graphics

Board display options	Supports two displays via included DMS-59 to dual VGA cable or 2 DVI monitors via optional DMS-59 to dual DVI cable kit part number: DL139A. 4-pin mini-DIN S-video connector for TV output	
Board configuration	Specification	Description
	Graphics Chip	RV710
	Core clock	600MHz
	Memory clock	800 MHz
	Frame buffer	256 MB DDR2, 64 bit wide
Languages supported	24 languages: English, Arabic, Chinese Simplified, Chinese Traditional, Czechoslovakian, Danish, Dutch, Finnish, French, German, Greek, Hebrew, Hungarian, Italian, Japanese, Korean, Norwegian, Polish, Portuguese, Russian, Spanish, Swedish, Thai, Turkish	
Compliance standards	Portuguese, Russian, Spanish, Swedish, Thai, Turkish <u>EMC Emissions</u> : a) FCC Part 15, Subpart B - Unintentional Radiators, Class B Computing Devices for Home & Office Use b) CISPR22: 1997/EN 55022:1998 - Class B - Limits and methods of measurement of radio disturbance characteristics of Information Technology Equipment c) Canadian Standard ICES-003 is equivalent to CISPR22 d) Taiwanese Standard BSMI e) Japanese VCCI f) Australian C-Tick g) Korean (KCC)	

EMC Immunity:

CISPR 24:1997/EN 55024:1998 - Information Technology Equipment -Immunity Characteristics - Limits and Methods of Measurement.

ATI Radeon HD 4550 DH PCle x16 Graphics Card display resolutions and refresh rates

NOTE: Other resolutions may be available but are not recommended as the may not have been tested and qualified by HP.

	Maximum Refresh Rate (Hz)	
Resolution	Analog Connection	Digital Connection
640x480	85	60
800x600	85	60
1024x768	85	60
1280x720	85	60
1280x1024	85	60
1440x900	75	60
1600x1200	85	60
1680x1050	75	60
1920x1080	85	60-R
1920x1200	85	60-R
1920x1440	85	N/A
2048x1536	75	N/A
2560x1600	N/A	N/A

NOTE: 60-R denotes reduced blanking timings are used on single-link DVI connections and may be used with other digital connections.



Technical Specifications - Graphics

NVIDIA Quadro NVS 290 PCIe x1 Graphics Card	NVIDIA Quadro NVS 290 Bus type PCle x1 PCle x1 Graphics Card Low profile, both ATX and low profile brackets included Graphics Controller Integrated Quadro 290 2D graphics processor unit (GPU)		w profile brackets included
			raphics processor unit (GPU)
	Memory	256 MB DDR2	
	Connector	Single high-density DMS-59	Flex Connector
	Dimensions	Low-profile, 2.586 x 6.6 in (6.57 x 16.76 cm)
	Multi-monitor support	Dual analog or digital (Singl (DVI support requires option	
	RAMDAC	Dual 350 MHz (integrated)	
	Maximum pixel clock	350 MHz	
	Overlay planes	One 1-bit Video overlay pla	ne
	High-definition Video Processor (HDVP)	DVD-ready motion compens Independent hardware color	controls for video overlay ersion (YUV 4:2:2 and 4:2:0)
	Input/Output connectors	DMS-59	
	Board display options	Supports two displays via included DMS-59 to dual VGA cable or 2 DVI monitors via optional DMS-59 to dual DVI-I single-link connectors cable kit part number: DL139A.	
	Board configuration	Specification	Description
		Description	G86-825
		Core clock	460 MHz
		Memory clock	400 MHz
		Frame buffer	256 MB DDR2, 64 bit wide

NVIDIA Quadro NVS 290 PCIe x1 Graphics Card display resolutions and refresh rates

NOTE: Other resolutions may be available but are not recommended as the may not have been tested and qualified by HP.



Technical Specifications - Graphics

	Maximum Refresh Rate (Hz)	
Resolution	Analog Connection	Digital Connection
640x480	85	60
800x600	85	60
1024x768	85	60
1280x720	85	60
1280x1024	85	60
1440x900	75	60
1600x1200	85	60
1680x1050	75	60
1920x1080	85	60-R
1920x1200	85	60-R
1920x1440	85	N/A
2048x1536	75	N/A
2560x1600	N/A	N/A

NVIDIA Quadro NVS 290	Form Factor	Low Profile
256MB Dual Head PCle	Bus Type	PCle x16
x16 Graphics Card	Memory	256 MB 400MHz DDR2 SDRAM unified frame buffer, Z-buffer and Texture storage
	Connector	DMS-59, includes DMS-59 to Dual DVI-I cable. DMS-59 to Dual VGA cable available as an option.
	Display Resolution Support	Dual integrated analog display controllers supporting up to two analog displays at 2048x1536 @ 85Hz on both displays or dual digital displays at 1920x1200 (single-link). nVIEW advanced multi-display desktop and application management seamlessly integrated into Microsoft Windows
	RAMDAC	Integrated dual 400MHz
	Color planes	32-bit color buffer
	Overlay planes	Hardware supported
	nView architecture	Advanced multi-display desktop & application management seamlessly integrated into Microsoft Windows.
	Multi-Monitor support	Dual monitor support
	DVI support	DMS-59 (to dual DVI-SL)
	High-definition Video Processor (HDVP)	Full-screen, full-frame video playback of HDTV and DVD content DVD-ready motion compensation for MPEG- 2Independent hardware color controls for video overlay Hardware color-space conversion (YUV 4:2:2 and 4:2:0) IDCT motion compensation 5-tap horizontal by 3-tap vertical filtering 8:1 up/down scaling
	Supported graphics APIs	OGL 2.1 & DX10 Support; Shader Model 4.0



Technical Specifications - Graphics

NVIDIA Quadro NVS 295 (256MB DH) PCle x 16 Graphics Card	Form Factor Graphics Controller Bus Type Memory Connectors	 2.731 inches (H) × 6.600 inches (L), Half-Height NVIDIA Quadro NVS 295 Graphics Board PCI Express x16, Generation 2.0 256 MB GDDR3 SDRAM unified graphics memory 2 DisplayPort Comes with 2 DisplayPort to VGA Adapters ('DisplayPort to DVI-D' and 'DisplayPort to DL DVI-D adapters available as an accessory)
	Maximum Resolution Display Output	 Two DisplayPort outputs drive two digital displays up to 2560 x 1600 Drives DisplayPort enabled digital displays at resolutions up to 2560 × 1600 at 60 Hz with reduced blanking Drives DVI enabled digital displays at resolutions up to 1920 × 1200 at 60 Hz with reduced blanking (through DisplayPort to DVI-D (single link) cable)
	Supported Graphics APIs	OpenGL 3.0 DirectX 10.0

NVIDIA GeForce	Bus type	PCI Express (x16 lanes)
310 DP PCIe x16 Graphics Card	Maximum vertical refresh rate	85 Hz
	Display support	Integrated 400 MHz RAMDAC
	Display max resolution	2560x1600 digital, 2048 x 1536 analog
	NVIDIA GeForce 310 [PPCIe x16 Graphics Card display resolut

NVIDIA GeForce 310 DP PCIe x16 Graphics Card display resolutions and refresh rates NOTE: Other resolutions may be available but are not recommended as the may not have been tested and gualified by HP.

Resolution	Maximum Refresh Rate (Hz)	
	Analog Connection	Digital Connection
640x480	85	60
800x600	85	60
1024x768	85	60
1280x720	85	60
1280x1024	85	60
1440x900	75	60
1600x1200	85	60
1680x1050	75	60
1920x1080	85	60-R
1920x1200	85	60-R
1920x1440	85	N/A
2048x1536	75	N/A
2560x1600	N/A	60*

* Only supported when using a dual-link DVI or DP connection.

NOTE: 60-R denotes reduced blanking timings are used on single-link DVI connections and may be used with other digital connections.

Board display options Supports two displays via the DisplayPort and DVI connectors



Technical Specifications - Graphics

Board configuration	Specification	Description
	Graphics Chip	RV620
	Core clock	750 MHz
	Memory clock	500 MHz
	Frame buffer	512 MB DDR3, 64 bit wide
Audio Support (through HDMI only)	Integrated HD Audio codec suppo formats for HDMI output	rts linear PCM and Dolby® Digital (7.1) audio
Operating systems support	Windows 7 Home Basic [*] , Windows 7 Home Premium [*] , Windows 7 Professional Edition 32 [*] , Windows 7 Professional Edition 64 [*] , Windows 7 Ultimate Edition 32 [*] , Windows 7 Ultimate Edition 64 [*] , Windows Vista Business 32 [†] , Windows Vista Business 64 [†] , Windows Vista Home Basic 32 [†] , Windows Vista Home Basic 64 [†] , Windows XP Professional or Windows XP Home 32 [†] .	
	DVD drive to install the Windows 7	d and/or separately purchased hardware and/or a 7 software and take full advantage of Windows 7 rosoft.com/windows/windows-7/ for details.
	this downgrade an end user must	ncluded for future upgrade if desired. To qualify for be a business (including governmental or rected to order at least 25 customer systems with the
	Windows Vista Upgrade Advisor co Vista will run on your computer. To http://www.windowsvista.com/upg	eatures require advanced or additional hardware. an help you determine which features of Windows o download the tool, visit: gradeadvisor. For Windows Vista system adowsvista.com/systemrequirements.
	Linux x86 and x86_64 distribution	s using XFree86 or X.Org‡.
	distribution. Refer to the Open Sou	ATI's website and may be available in a Linux urce and Linux from HP website: inux/products/clients/ for support information.
Core power	22 W (max)	
Dimensions (H x D)	2.71 in x 6.60 in (68.90 mm x 16	7.65 mm)
Weight	0.30 lb (134.3 g)	
Option kit contents	attached • DVI to VGA adapter • Software CD with graphics of	Cle x16 Graphics Cardwith full height bracket drivers ert the card for using in a low profile chassis
Compliance standards	Home & Office Use b) CISPR22: 1997/EN 55022:199	entional Radiators, Class B Computing Devices for 98 - Class B - Limits and methods of measurement s of Information Technology Equipment s equivalent to CISPR22



Technical Specifico	ations - Graphic	s			
		e) Japanese VCCI f) Australian C-Tick g) Korean (MIC)			
			l 55024:1998 - Infor nits and Methods of N	mation Technology Eq Aeasurement.	uipment - Immunity
HP ADD2 SDVO PCIe	Models	HP ADD2	SDVO DVI-D Out Add	apter	
DVI-D Adapter	Form Factor	Low-profile	e card		
	DVI-D Connecte	or Digital con	nection only		
	Dual Head Sup	port Yes, when	used with the integrat	ed VGA connector	
	Display Devices Supported	HP L1740 HP L1940 HP L2045 HP L2045 HP LP1965	N		
	NOTE: These gr standards.	raphics adapters offer	optimal performance	with any display that m	neets applicable VESA
	Color Depth	All modes	support 8-bpp, 16-bp	p, and 24-bpp color c	lepths
	Host Interface C	Connector Mechanica Complies v specificatic	with the Intel ADD2 ar	I-E standard nd Intel Serial Digital V	ideo Output (SDVO)
	Dot Clock	165 MHz r	naximum		
	Display Modes		isplay modes that req n the following table.	uire up to 165-MHz bo	andwidth on the link,
Resolu	tion	60-Hz LCD	60-Hz	75-Hz	85-Hz
Blank	ing	5% reduced	GTF	GTF	GTF
640 x 480	VGA	Yes	Yes	Yes	Yes
800 x 600	SVGA	Yes	Yes	Yes	Yes
1024 x 768	XGA	Yes	Yes	Yes	Yes
1280 x 1024	SXGA	Yes	Yes	No	No
1600 x 1200	UXGA	Yes	Yes	No	No

HP DisplayPort to DVI-D Connector Adapter Adapter Id

Connectors Adapter length Adapter weight DisplayPort and DVI-D single link connector 7.5 in (19.0 cm) .10 lbs (.05 kg)



Technical Specifications - Graphics

HP DisplayPort to VGA	Connectors	DisplayPort and VGA connector
Adapter	Adapter length	8 in (20 cm)
	Adapter weight	.1 lbs (.06 kg)
	Maximum vertical refresh rate	85 Hz
	Display support	162 MHz RAMDAC
	Display max resolution	1600x1200

HP DisplayPort to VGA adapter display resolutions and refresh rates

NOTE: Other resolutions may be available but are not recommended as they may not have been tested and gualified by HP. Using the HP DisplayPort to VGA Adapter may require an update to the graphics driver installed on your system. To install the most up-todate graphics driver go to: www.hp.com.

Resolution	Max refresh rate	
640x480	85	
800x600	85	
1024x768	85	
1280x720	85	
1280x1024	85	
1440x900	75	
1600x1200	60	
1680x1050	60	
1920x1080	60-R	
1920x1200	60-R	
NOTE: 60-R denotes reduced blanking timings are used. Not all monitors support reduced blanking timing.		



Technical Specifications - Internal Storage

7200 RPM Serial ATA Hard Drives	500-GB	Capacity Height Width Interface Synchronous Transfer Rate (Maximum) Buffer	500,107,862,016 bytes 1 in (2.54 cm) Media diameter: 3.5 in (8 Physical size: 4 in (10.2 cm Serial ATA (3.0 Gb/s) Up to 3 Gb/s	,
			16 MB Signala Tagala	2.0 ms
		Seek Time (typical reads, includes controller	Single Track	2.0 ms
		overhead, including	Average Full-Stroke	21 ms
		settling) Potational Speed		21 1110
		Rotational Speed Logical Blocks	7,200 rpm 976,773,168	
		Operating Temperature	41° to 131° F (5° to 55° C	
		e poraning romporatoro		-1
	320-GB	Capacity	320,072,933,376 bytes	
		Height	1 in (2.54 cm)	
		Width	Media diameter: 3.5 in (8 Physical size: 4 in (10.2 cr	
		Interface	Serial ATA (3.0 Gb/s)	
		Synchronous Transfer Rate (Maximum)	Up to 3 Gb/s	
		Buffer	8 MB	
		Seek Time (typical reads,	Single Track	1.0 ms
		includes controller overhead, including	Average	8.5 ms
		settling)	Full-Stroke	18 ms
		Rotational Speed	7,200 rpm	
		Logical Blocks	625,142,448	
		Operating Temperature	41° to 131° F (5° to 55° C	2)
	250-GB	Capacity	250,059,350,016 bytes	
		Height	1 in (2.54 cm)	
		Width	Media diameter: 3.5 in (8 Physical size: 4 in (10.2 cr	,
		Interface	Serial ATA (3.0 Gb/s)	
		Synchronous Transfer Rate (Maximum)	Up to 3 Gb/s	
		Buffer	8 MB	



Technical Specifications - Internal Storage

		-		
		Seek Time (typical reads,	Single Track	1.0 ms
		includes controller	Average	8.5 ms
		overhead, including settling)	Full-Stroke	18 ms
		Rotational Speed	7,200 rpm	
		Logical Blocks	488,397,168	
		Operating Temperature	41° to 131° F (5° to 55°	C)
	160-GB	Capacity	160,041,885,696 bytes	
		Height	1 in (2.54 cm)	
		Width	Media diameter: 3.5 in (Physical size: 4 in (10.2 c	
		Interface	Serial ATA (3.0 Gb/s)	
		Synchronous Transfer Rate (Maximum)	Up to 3 Gb/s	
		Buffer	8 MB	
		Seek Time (typical reads,	Single Track	0.9 ms
		includes controller overhead, including	Average	9.3 ms
		settling)	Full-Stroke	18 ms
		Rotational Speed	7,200 rpm	
		Logical Blocks	312,581,808	
		Operating Temperature	41° to 131° F (5° to 55°	C)
10,000 RPM Serial ATA	160-GB	Capacity	160,041,885,696 bytes	
Hard Drives		Height	1 in (2.54 cm)	
		Width	Media diameter: 2.5 in (Physical size: 4 in (10.2 c	
		Interface	Serial ATA (1.5 Gb/s), N	ative Command Queuing enabled
		Synchronous Transfer Rate (Maximum)	Up to 3.0 Gb/s	
		Cache	16 Mbytes	
		Seek Time (typical reads,	Single Track	0.3 ms
		includes controller overhead, including	Average	4.6 ms
		settling)	Full-Stroke	10.2 ms
		Rotational Speed	10,000 rpm	
		Logical Blocks	312,581,808	
		Operating Temperature	41° to 131° F (5° to 55°	C)
	80-GB	Capacity	80,026,361,856 bytes	
		Height	1 in (2.54 cm)	
		Width	Media diameter: 2.5 in (2 cm)



Technical Specifications - Internal Storage

Interface	Serial ATA (1.5 Gb/s), Native Command Queuing enabled	
Synchronous Transfer Rate (Maximum)	Up to 3.0 Gb/s	
Cache	16 Mbytes	
Seek Time (typical reads,	Single Track	0.3 ms
includes controller	Average	4.6 ms
overhead, including settling)	Full-Stroke	10.2 ms
Rotational Speed	10,000 rpm	
Logical Blocks	156,301,488	
Operating Temperature	41° to 131° F (5° to 55° (C)

64 GB Solid State Drive	Capacity	64 GB	
	NAND Flash Memory	Multi Level Cell (MLC) with) wear leveling controller
	Interface type	SATA 3Gb/sec	
	Dimensions-external (W x H x D)	2.74 x 0.37 x 4 in (6.98 x	0.95 x 10.2 cm)
	Weight	0.14 lb (65 g)	
	Internal transfer rate	Write speed	Up to 220 MB/s
		Read speed	Up to 120 MB/s
	Host transfer rate	Ultra DMA mode	Up to 150 MB/s
	Power	DC power requirement	5 VDC 5%-100 mV ripple p-p
		Total power consumption	<1.12Watt
	Environmental	Temperature (operating)	32° to 158° F (0° to 70° C)
	(all conditions, non- condensing)	Relative Humidity (operating)	5% to 95%
		Maximum Wet Bulb Temperature (operating)	84° F (29° C)
	Regulations	UL, CSA, EN 60950-2000 CISPR 22:2002 Class B, R), CISPR Pub 22 Class B, CNS 13438, AS/NZS 1113 and C1172 Class B
	* For solid state disk drives	GB magns 1 billion bytes	16GB is the unformatted capacity of this drive

* For solid state disk drives, GB means 1 billion bytes. 16GB is the unformatted capacity of this drive before a portion of the drive is reserved for flash management features. Actual capacity varies by content and will be less than 15.8GB.



USB

Technical Specifications - Input/Output Devices

3 Standard Keyboard	Physical characteristics	Keys	104, 105, 106, 107, 109 layout (depending upon country)
		Dimensions (L \times W \times H)	18.0 x 6.4 x 0.98 in (45.8 x 16.3 x 2.5 cm)
		Weight	2 lb (0.9 kg) minimum
	Electrical	Operating voltage	$+$ 5VDC \pm 5%
		Power consumption	50-mA maximum (with three LEDs ON)
		System interface	USB Type A plug connector
		ESD	CE level 4, 15-kV air discharge
		EMI - RFI	Conforms to FCC rules for a Class B computing device
		Microsoft® PC 99 - 2001	Functionally compliant
	Mechanical	Languages	38 available
		Keycaps	Low-profile design
		Switch actuation	55-g nominal peak force with tactile feedback
		Switch life	20 million keystrokes (using Hasco modified tester)
		Switch type	Contamination-resistant switch membrane
		Key-leveling mechanisms	For all double-wide and greater-length keys
		Cable length	6 ft (1.8 m)
		Microsoft PC 99 - 2001	Mechanically compliant
		Acoustics	43-dBA maximum sound pressure level
	Environmental	Operating temperature	50° to 122° F (10° to 50° C)
		Non-operating temperature	-22° to 140° F (-30° to 60° C)
		Operating humidity	10% to 90% (non-condensing at ambient)
		Non-operating humidity	20% to 80% (non-condensing at ambient)
		Operating shock	40 g, six surfaces
		Non-operating shock	80 g, six surfaces
		Operating vibration	2-g peak acceleration
		Non-operating vibration	4-g peak acceleration
		Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
		Drop (in box)	42 in (107 cm) on concrete, 16-drop sequence
	Approvals	UL, CSA, FCC, CE Mark,	TUV, TUV GS, VCCI, BSMI, C-Tick, MIC
	Ergonomic compliance	ANSI HFS 100, ISO 9241	
	Kit contents	Keyboard, installation guid	de, warranty card, safety and comfort guide



invent

PS/2 Standard Keyboard	Physical characteristics	Keys	104, 105, 106, 107, 109 layout (depending upon country)
		Dimensions $(L \times W \times H)$	18.0 x 6.4 x 0.98 in (45.8 x 16.3 x 2.5 cm)
		Weight	2 lb (0.9 kg) minimum
	Electrical	Operating voltage	$+$ 5VDC \pm 5%
		Power consumption	50-mA maximum (with three LEDs ON)
		System interface	PS/2 6-pin mini din connector
		ESD	CE level 4, 15-kV air discharge
		EMI - RFI	Conforms to FCC rules for a Class B computing device
		Microsoft PC 99 - 2001	Functionally compliant
	Mechanical	Languages	38 available
		Keycaps	Low-profile design
		Switch actuation	55-g nominal peak force with tactile feedback
		Switch life	20 million keystrokes (using Hasco modified tester)
		Switch type	Contamination-resistant switch membrane
		Key-leveling mechanisms	For all double-wide and greater-length keys
		Cable length	6 ft (1.8 m)
		Microsoft PC 99 - 2001	Mechanically compliant
		Acoustics	43-dBA maximum sound pressure level
	Environmental	Operating temperature	50° to 122° F (10° to 50° C)
		Non-operating temperature	-22° to 140° F (-30° to 60° C)
		Operating humidity	10% to 90% (non-condensing at ambient)
		Non-operating humidity	20% to 80% (non-condensing at ambient)
		Operating shock	40 g, six surfaces
		Non-operating shock	80 g, six surfaces
		Operating vibration	2-g peak acceleration
		Non-operating vibration	4-g peak acceleration
		Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
		Drop (in box)	42 in (107 cm) on concrete, 16-drop sequence
	Approvals	UL, CSA, FCC, CE Mark,	TUV, TUV GS, VCCI, BSMI, C-Tick, MIC
	Ergonomic compliance	ANSI HFS 100, ISO 9241	-4, and TUVGS
HP USB Smartcard Keyboard	Physical characteristics	Keys	104, 105, 106, 107, 109 layout (depending upon country)
		Form factor	USB basic Smart Card keyboard
		Colors	Carbonite/Silver
		Dimensions (H \times W \times D)	18.2 x 6.3 x 1.3 in (46.3 x 16.1 x 3.3 cm)
		Weight	2 lb (0.9 kg) minimum
	Electrical	Operating voltage	$+$ 5VDC \pm 5%

Technical Specifications - Input/Output Devices

1 , 1		
	Power consumption	100-mA maximum (with four LEDs ON)
	System interface	USB Type A plug connector
	ESD	CE level 4, 15-kV air discharge
	EMI - RFI	Conforms to FCC rules for a Class B computing device
	Microsoft PC 99 - 2001	Functionally compliant
Mechanical	Languages	30+ available
	Keycaps	Low-profile design
	Switch actuation	55 g nominal peak force with tactile feedback
	Switch life	20 million keystrokes (using Hasco modified tester)
	Switch type	Contamination-resistant membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	6 ft (1.8 m)
	Microsoft PC 99 - 2001	Mechanically compliant
	Acoustics	43-dBA maximum sound pressure level
Environmental	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	42 in (107 cm) on concrete, 16-drop sequence
SMARTCARD function	Support	All ISO 7816 smart cards
	Interface	Reads from and writes to all ISO7816-1, 2, 3, 4 memory and microprocessor smart cards (T=0, T=1)
	Chipset	SCM STCII
	Standard APIs supported	PC/SC, EMV2000, SET
	Power	USB Port
		Short circuit detection (protects smart card and
	Power consumption	reader) Power supply compliant with ISO7816 and EMV (5V, 60 mA) Supports 3-V and 5-V cards 250-mA maximum draw (50 mA for the
		keyboard with three LEDs ON and 200-mA maximum startup current using a high-current, 60-mA smart card)



Technical Specifications - Input/Output Devices

reennear opeemean		vices			
		Communication	From card	Programmable from 9,600 baud to 115,200 baud	
			From computer	Up to 38,400 baud	
		Landing mechanism	Contact device	Friction contact	
			Card insertions rating	Up to 100,000 insertion cycles	
		Si A	SCM protocol	USB communications through USB port	
			USB connection		
		Electro-magnetic	Europe	89/336/CEE guideline	
		standards	USA	USAFCC part 15	
HP USB 2-Button Laser	Scroll Wheel	24			
Mouse	Maximum Rotation Speed	48 rats/sec			
	Switch Type	wheel			
	Switch Life	Button - 3,000,000 Wheel - 1,000,000 times Tilt switch - 500,000 times	5		
	Environmental	Operating Temperature	32° to 104° F (0 $^\circ$ to 40	° C)	
		Non-operating Temperature	-4° to 140° F (-20° to 6	0° C)	
		Operating Humidity	10% to 90% (non-cond	ensing at ambient)	
		Non-operating Humidity	20% to 80% (non-cond	ensing at ambient)	
		Operating Shock	40 g, six surfaces		
		Non-operating Shock	80 g, six surfaces		
		Operating Vibration	2-g peak acceleration		
		Non-operating Vibration	4-g peak acceleration		
	Electrical	Operating Voltage	$+$ 5VDC \pm 5%		
		Power Consumption			
		MTBF	> 150,000 hrs		
		ESD	IEC-61000-4-2 criteria +/- 4kV, Air discharge:		
		EMI-RFI	FCC Class B		
		PC98	PC 99 Compliant		
	Mechanical	Resolution	800dpi		
		Tracking Speed	25 cm/sec		
		Acceleration	0.5mm		
		Switch Actuation	0.6N (60gf)		



Technical Specifications - Input/Output Devices

		Switch Life	Button - 3,000,000 Wheel - 1,000,000 times Tilt switch - 500,000 times	
		Cable Length	, 1850mm	
		PC98-99	PC99 compliant	
	Regulatory Approvals	UL60950-1, UL 94, UL 74 TUV/GS: EN 60950-1, EN FCC Class B, UL 1950, cl		
HP PS/2 Optical Scroll	Dimensions (H x L x W)	3.95 x 6.21 x 11.7 cm (1.56 x 2.44 x 4.61 in) 4.44 oz (126 g)		
Mouse	Weight			
	Environmental	Operating temperature	-32° to 104°F (0° to 40° C)	
		Non-operating temperature	-4° to 140°F (-20° to 60° C)	
		Operating humidity	10% to 90% (non condensing at ambient)	
		Non-operating humidity	10% to 90% non condensing	
		Operating shock	40 g, 6 surfaces	
		Non-operating shock	80 g, 6 surfaces	
		Operating vibration	2 g peak acceleration	
		Non-operating vibration	4 g peak acceleration	
		Drop (out of box)	80 cm height onto asphalt tile over concrete or equivalent, 5-drop in 5 direction except the cable face	
	Electrical	Operating voltage	5 VDC ± 10%	
		Power consumption	100mA	
		System consumption	PS/2 mini-din connector	
		ESD	CE level 4, 15 kV air discharge	
		EMI-RFI	Conforms to FCC rules for a Class B computing device	
		Microsoft PC99 - 2001	Functionally compliant	
	Mechanical	Resolution	$400 \pm 20\%$ DPI	
		Tracking speed	10 in/s (25.4 cm/s) maximum	
		Acceleration	100 in/s/s (2.54 m/s/s)	
		Switch actuation	61 g nominal peak force	
		Switch life	3,000,000 operations (using Hasco modified tester)	
		Switch type	Low force micro-switches	
		Tracking mechanism life	155 mi (250 km) at average speed of 10 in/s	
		Cable length	6 ft (1.8 m)	
		Microsoft PC99 - 2001	Mechanically compliant	
	Scroll wheel	Width	8 mm	
		Diameter	1.01 in (25.6 mm)	
~ / ~		Maximum rotation speed	48 rats/sec	



Technical Specifications - Input/Output Devices

Cable length

		Switch type Switch life	Light force micro-switch 1 million operations
	Regulatory approvals	Mechanical life Compliant	Minimum 200,000 revolutions UL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC
HP USB Optical Scroll Mouse	Dimensions (H x L x W) Weight	1.5 x 4.5 x 2.5 in (3.8 x 0.27 lb (0.12 kg)	11.6 x 6.3 cm)

72.8 in (185 cm)



Technical Specifications - Optical Storage

HP SATA Blu-ray Writer	Height Orientation Interface type Disc capacity Dimensions (W x H x D) Weight (max)	tray-load ical indard ix 4.4 x 19.0 cm)		
			Single-layer	Double-layer
	Write speed	BD-R	2x, 4x CLV, 6x CAV	2x, 4x CLV
		BD-RE	2.3x	2x CLV
		DVD-R	2x, 4x CLV, 8x ZCLV, 8x 12x PCAV, 16x CAV	, 2x, 4x CLV
		DVD-RW	1x, 2x, 4x, 6x CLV	Not supported
		DVD+R	2.4x, 4x CLV, 8x ZCLV, 8x, 12x PCAV, 16x CAV	2.4x, 4x CLV
		DVD+RW	2.4x, 4x, 6x CLV, 8x ZCLV	Not supported
		DVD-RAM	2x, 3x CLV, 3-5x PCAV	
		CD-R	8x,16x CLV, 24x, 32x P	CAV, 40x CAV
		CD-RW	4x, 10x, 16x CLV, 24x Z	CLV
			Single-layer	Double-layer
	Read speeds	BD-ROM	6x CAV	4.8x CAV
		BD-R	6x CAV	4.8x CAV
		BD-RE (SL/DL)	4.8x CAV	4.8x CAV
		DVD-ROM	16x CAV	8x CAV
		DVD-R	12x CAV	8x CAV
		DVD-RW	10x CAV	Not support
		DVD+R	12x CAV	8x CAV
		DVD+RW	10x CAV	Not support
		BDMV (AACS Compliant Disc)	4.8x CAV	
		DVD-RAM	2x, 3x CLV, 3x-5x PCAV	
		DVD-Video (CSS Compliant Disc)	8x CAV	
		CD-R/RW/ROM	40x / 40x / 40x CAV	
		CD-DA (DAE)	32x CAV	
		80 mm CD	16x CAV	
	Sustained Transfer rate	BD-ROM	215.79 Mbits/s (6x) max	κ.
		DVD-ROM	16.62 Mbytes/s (16x) m	ax.
		CD-ROM	6,000 KB/s (40x) max.	
	Burst Transfer rate		1.5Gbps bits/s (10b side 1.2Gbps bits/s (8b side)	



HP Compaq 6000 Pro Business PC

Technical Specifications - Optical Storage

	Multimedia MPC-3 compliant		Yes	
	Access times	Random	DVD: < 140 ms (typical), CD: < 125 ms (typical)	
	(typical reads, including setting)	Full Stroke	DVD: < 250 ms (seek), CD: < 210 ms (seek)	
	Power	Source	SATA DC power receptacle	
		DC Power Requirement	5 VDC ± 5%-100 mV ripple p-p 12 VDC ± 5%-200 mV ripple p-p	
		DC Current	5 VDC -1000 mA typical, 1600 mA maximum 12 VDC -600 mA typical, 1400 mA maximum	
	Environmental	Temperature (operating)	41° to 122° F (5° to 50° C)	
	(all conditions non-condensing)	Relative Humidity (operating)	10% to 90%	
		Maximum Wet Bulb	86° F (30° C)	
		Temperature (operating)		
HP SATA SuperMulti	Height	5.25-inch, half-height, tro	ay-load	
LightScribe DVD Writer	Orientation	Either horizontal or vertic	-	
Drive	Interface type	SATA/ATAPI		
	Disc capacity	8.5 GB DL or 4.7 GB standard		
	Dimensions ($W \times H \times D$)	5.9 x 1.7 x 8.0 in (15.0 x 4.4 x 20.3 cm)		
	Weight (max)	2.6 lb (1.2 kg)		
	Write speeds	DVD-RAM	Up to 12X	
	•	DVD+R	Up to 16X	
		DVD+RW	Up to 8X	
		DVD+R DL	Up to 8X	
		DVD-R DL	Up to 8X	
		DVD-R	Up to 16X	
		DVD-RW	Up to 6X	
		CD-R	Up to 48X	
		CD-RW	Up to 32X	
	Read speeds	DVD-RAM	Up to 12X	
		DVD+RW, DVD-RW, DVD+R DL, DVD-R DL	Up to 8X	
		DVD-ROM DL	Up to 8X	
		DVD-ROM, DVD+R, DVD-R	Up to 16X	
		CD-ROM, CD-R	Up to 48X	
		CD-RW	Up to 32X	
	Access time (typical reads, including	Random	DVD: < 140 ms (typical), CD: < 125 ms (typical)	
	settling)	Full Stroke	DVD: < 250 ms (seek), CD: < 210 ms (seek)	
	Power	Source	SATA DC power receptacle	



Technical Specificati	ions - Optical Storage				
		DC Power Requirement	5 VDC ± 5%-100	mV ripple p-p	
			12 VDC ± 5%-200) mV ripple p-p	
		DC Current	5 VDC (< 1000 m. maximum)	A typical, 1600 mA	
			12 VDC (< 600 m. maximum)	A typical, 1400 mA	
	Environmental conditions	Temperature	41° to 122° F (5° to	⊳ 50° C)	
	(operating - non-	Relative Humidity	10% to 90%	,	
	condensing)	Maximum Wet Bulb Temperature	86° F (30° C)		
ATA DVD-ROM Drive	Height	5.25-inch, half-height, tro	ıy-load		
	Orientation	Either horizontal or vertical			
	Interface type	SATA/ATAPI			
	Disc capacity	Single layer: Up to 4.7 GB (6 times capacity of CD-ROM) Double layer: Up to 8.5 GB (12 times capacity of CD-ROM)			
	Dimensions ($W \times H \times D$)	5.9 x 1.7 x 8.0 in (15.0 x 4.4 x 20.3 cm)			
	Weight (max)	2.6 lb (1.2 kg)			
	Read speeds	DVD+R/-R/+RW/ -RW/+R DL /-R DL	Up to 8X		
		DVD-ROM	Up to 16X		
		DVD-RAM	Up to 4X		
		CD-ROM, CD-R	Up to 48X		
		CD-RW	Up to 32X		
	Removable Storage - Media Compatibility -	Media	Read	Write	
		CD-ROM	Yes	No	
	DVD-ROM	CD-R	Yes	No	
		CD-RW	Yes	No	
		DVD-ROM	Yes	No	
		DVD-ROM DL	Yes	No	
		DVD-RAM	Yes	No	
		DVD+R	Yes	No	
		DVD+R DL	Yes	No	
		DVD+RW	Yes	No	
		DVD-R	Yes	No	
		DVD-RW	Yes	No	
		DVD-R DL	Yes	No	
	Access times (typical reads, including	Random	DVD: < 140 ms (ty (typical)	rpical), CD: < 125 ms	
	setting)	Full Stroke	DVD: < 250 ms (seek), CD: < 210 ms (seek)		
		Cache Buffer	2 MB (minimum)		



Technical Specifications - Optical Storage

	Data Transfer Modes	ATA PIO mode 4 (16.7 MB/s); ATA Multi-word DMA mode 2 (16.7 MB/s); ATA UltraDMA Mode 3 (44.4 MB/s -default)
Power	Source	SATA DC power receptacle
	DC Power Requirement	5 VDC \pm 5%-100 mV ripple p-p 12 VDC \pm 5%-200 mV ripple p-p
	DC Current	5 VDC - <1000 mA typical, < 1600 mA maximum 12 VDC -< 600 mA typical, < 1400 mA maximum
Environmental	Temperature	41° to 122° F (5° to 50° C)
(all conditions	Relative Humidity	10% to 90%
non-condensing)	Maximum Wet Bulb Temperature	86° F (30° C)



Technical Specifications - Removable Storage

HP 22-in-1 (with 1394) Media Card Reader	USB Interface	USB 2.0 High-speed interfo	ace
		NOTE: Requires the USB co or a USB 2.0 PCI card.	able to be connected to the internal USB 2.0 port
	1394 Interface	Two IEEE-1394a external p pass through cable on the	oorts; 1 IEEE-1394a internal port (connects to the media card reader)
	Advance protocol support	 Supports hardware CRC (Cyclic Redundancy Check) function Supports MS 4-bit parallel transfer mode Supports MS-PRO 4-bit parallel transfer mode Supports MS PRO-HG Duo 4-bit parallel transfer mode Supports SD 4-bit parallel transfer mode Supports high-speed 50Mhz SD 4-bit card (version 2.0) Supports high-speed 52Mhz MMC 8-bit card (version 4.2) Supports CF v4.0 with PIO mode 6 and Ultra DMA mode 	
	Supported media type		II MC) MediaCard (RS MMC) (MMC Plus, including MMC Plus HC) MediaCard 4.2 (MMC Mobile, including MMC (SD) Capacity (SDHC) (SD) Capacity (SDHC) (MS PRO) Duo (MS PRO Duo) HG Duo Stick (MG)
	Supported media type with card adapter	Memory Stick MicroMMC Micro	(M2)
	Environmental	Operational Environmental Extremes	Test Parameters/Conditions - Power applied, unit operating on system $\pm 5\%$ nominal supply voltage. 10°C 10% R.H. = 24 hours 10°C 90% R.H. = 24 hours 20°C 90% R.H. = 24 hours



30°C 90% R.H. = 24 hours 40°C 90% R.H. = 24 hours 50°C 90% R.H. = 24 hours

Technical Specifications -	Removable Storage
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Approvals

	50°C 10% R.H. = 24 hours
Storage Environmental	Test Parameters/Conditions
Extremes	140°F (60°C) @ 80% R.H. for 96 hours
	-22°F (-30°C) @ 20% R.H. for 48 hours
	No power applied
	Delta °C < 1.0°C/min
	Delta % R.H. < 1.5% R.H./min
	nt with USB Mass Storage Class Bulk only Transport ompliant Intel Front Panel I/O Connectivity Design
FCC, CE, BSMI, C-Tick, \	/CCI, MIC, cUL, TUV-T



Technical Specifications - Environmental Data

Microtower

			
Eco-Label Certifications and declarations	This product has received or is in t labeled with one or more of these	he process of being certified to the for marks:	ollowing approvals and may be
	 US Energy Star IT ECO declaration EPEAT – Gold 		
System Configuration	The configuration used for the Ene Microtower model is based on a ty	rgy Consumption and Declared Nois pically configured product.	se Emissions data for the
Energy Consumption	115 VAC	230 VAC	100 VAC
Normal Operation	30.1794 W	30.3597 W	30.4591 W
Sleep (Energy Star low power mode)	2.4888 W	2.6405 W	2.4643 W
Off	0.7565 W	0.8930 W	0.7409 W
Heat Dissipation*	115 VAC	230 VAC	100 VAC
Normal Operation	103 BTU/hr	104 BTU/hr	104 BTU/hr
Sleep	8 BTU/hr	9 BTU/hr	8 BTU/hr
Off	3 BTU/hr	3 BTU/hr	2 BTU/hr
* Heat dissipation is calcu	lated based on the measured watts,	assuming the service level is attained	d for one hour.
Declared Noise Emission (in accordance with ISO 7779 and ISO 9296) System Fan Off Idle Fixed Disk (random writes)		Sound Pressure (LpAm, decibels) 27 28	
Batteries	This battery(s) in this product comp	bly with EU Directive 2006/66/EC	
	Batteries used in the product do no	ot contain:	
	Mercury greater the 5ppm bCadmium greater than 10p		
	Battery size: CR2032 (coin cell) Battery type: Li Ion		
Additional Information	 2002/95/EC. This HP product is designed Directive – 2002/96/EC. This product is in compliance Water and Toxic Enforceme This product is in compliance www.epeat.net 	te with the Restrictions of Hazardous to comply with the Waste Electrical of the with California Proposition 65 (Sta nt Act of 1986). The with the IEEE 1680 (EPEAT) stando 25 grams used in the product are m	and Electronic Equipment (WEEE) Ite of California; Safe Drinking ard at the Gold level, see



Technical Specifications - Environmental Data

ISO1043.

- This product contains 0% post consumer recycled plastic (by wt.)
- This product is 91.3% recyclable when properly disposed of at end of life.

Packaging Materials	External
---------------------	----------

Corrugated Paper	1835 g
Internal	
Polyethylene low density solid	150 g
Polyethylene low density foam	20 g

- The Polyethylene low density foam packaging material is made from 100% recycled content.
- The Polyethylene low density Solid packaging material is made from 100% recycled content.
- The corrugated packaging material contains at least 30% recycled content.

Small Form Factor

Eco-Label Certifications & This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- US Energy Star
- IT ECO declaration
- EPEAT Silver

System Configuration

ration The configuration used for the Energy Consumption and Declared Noise Emissions data for the Small Form Factor model is based on a typically configured product.

Energy Consumption	115 VAC	230 VAC	100 VAC
Normal Operation	29.5659 W	28.7916 W	29.1392 W
Sleep (Energy Star low power mode)	2.4243 W	2.6419 W	2.4196 W
Off	0.7496 W	0.9092 W	0.7371 W
Heat Dissipation*	115 VAC	230 VAC	100 VAC
Normal Operation	101 BTU/hr	98 BTU/hr	100 BTU/hr
Sleep	8 BTU/hr	9 BTU/hr	8 BTU/hr
Off	2 BTU/hr	3 BTU/hr	3 BTU/hr

* Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions

(in accordance with ISO 7779 and ISO 9296)

	Sound Power	Sound Pressure
System Fan Off	(LWAd, bels)	(LpAm, decibels)
ldle	3.8	27
Fixed Disk (random	3.9	28
writes)		



Technical Specifications - Environmental Data

Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC		
	Batteries used in the product do not contain:		
	Mercury greater the 5ppm by weightCadmium greater than 10ppm by weight		
Additional Information	 Battery size: CR2032 (coin cell) Battery type: Li Ion This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2002/95/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). 		
	 This product is in compliance with the IEEE 1680 (EPEAT) standard at the Silver level, see www.epeat.net Plastics parts weighing over 25 grams used in the product are marked per ISO 11469 and 		
	 ISO1043. This product contains 0% post consumer recycled plastic (by wt.) This product is 95.1% recyclable when properly disposed of at end of life. 		
	Packaging Materials External		
	Corrugated Carton 1705 g		
	Internal		
	EPE-Expanded Polyethylene 198 g		
	Polyethylene low density foam 39 g		
	 The EPE-Expanded Polyethylene packaging material is made from 100% recycled content. The Polyethylene low density foam packaging material is made from 100% recycled content. The Corrugated Carton packaging materials contains at least 75% recycled content. 		
Small Form Factor and	l Microtower		
RoHS Compliance	Hewlett-Packard is committed to compliance with all applicable environmental laws and regulations, including the European Union Restriction of Hazardous Substances (RoHS) Directive. HP's goal is to exceed compliance obligations by meeting the requirements of the RoHS Directive on a worldwide basis. By July 1, 2006, RoHS substances will be virtually eliminated (virtually = to levels below legal limits) for all HP electronic products subject to the RoHS Directive, except where it is widely recognized that there is no technically feasible alternative (as indicated by an exemption under the EU RoHS Directive).		
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):		
	 Asbestos Certain Azo Colorants Certain Brominated Flame Retardants – may not be used as flame retardants in plastics Cadmium Chlorinated Hydrocarbons Chlorinated Paraffins Formaldehyde 		

• Halogenated Diphenyl Methanes



Technical Specifications - Environmental Data

- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling To recycle your product, please go to: http://www.hp.com/recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

 Hewlett-Packard
 For more information about HP's commitment to the environment:

 Corporate Environmental
 Global Citizenship Report

 Information
 http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

 Eco-label certifications
 http://www.hp.com/hpinfo/globalcitizenship/environment/productdesign/ecolabels.html

 ISO 14001 certificates:
 http://www.hp.com/hpinfo/globalcitizenship/environment/operations/envmanagement.html



Technical Specifications - Environmental Data

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